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FIG. 1A

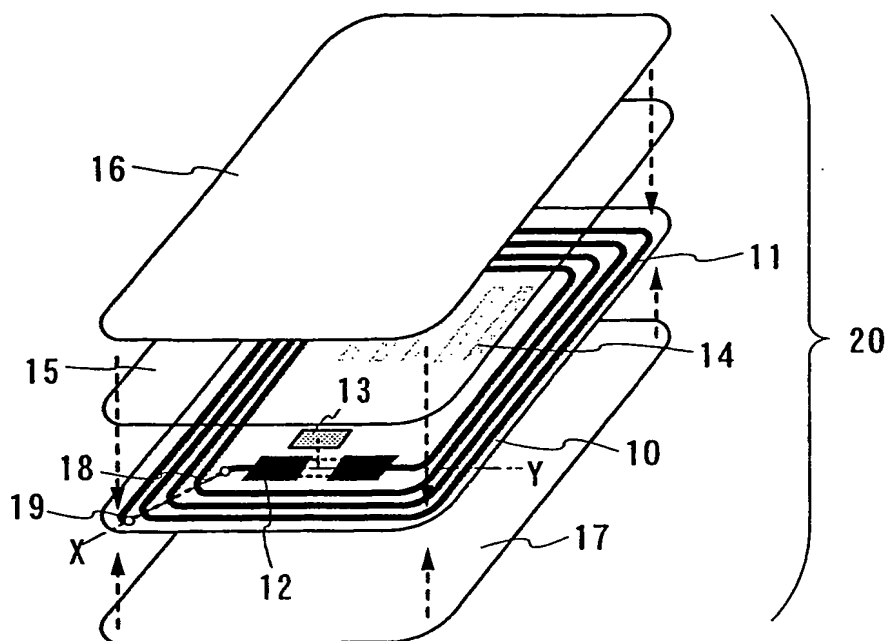


FIG. 1B

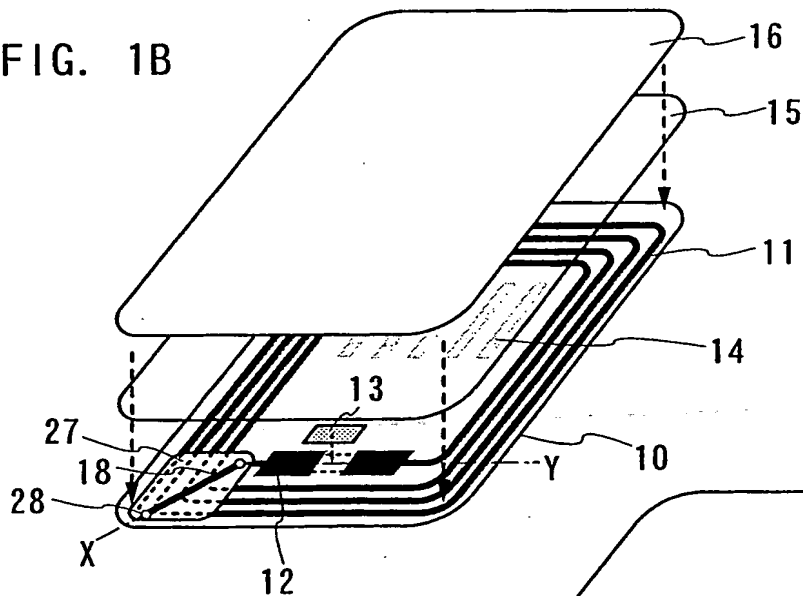
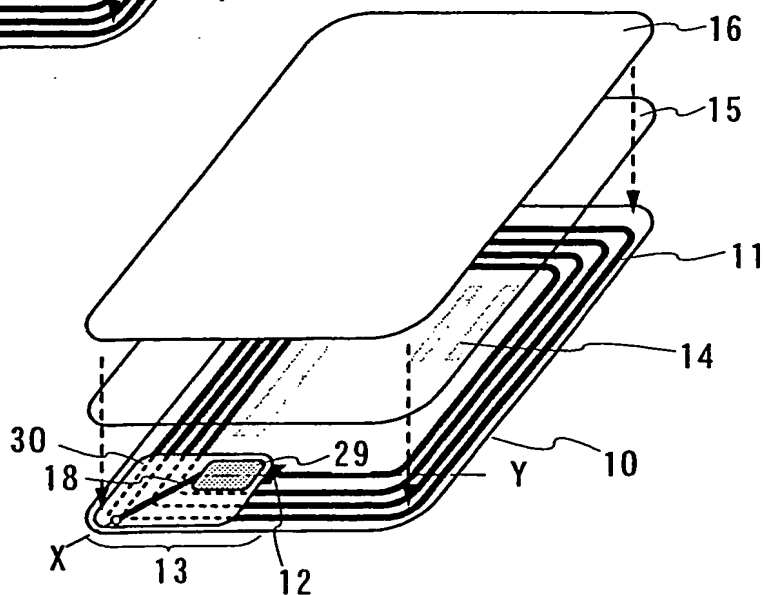


FIG. 1C



BEST AVAILABLE COPY

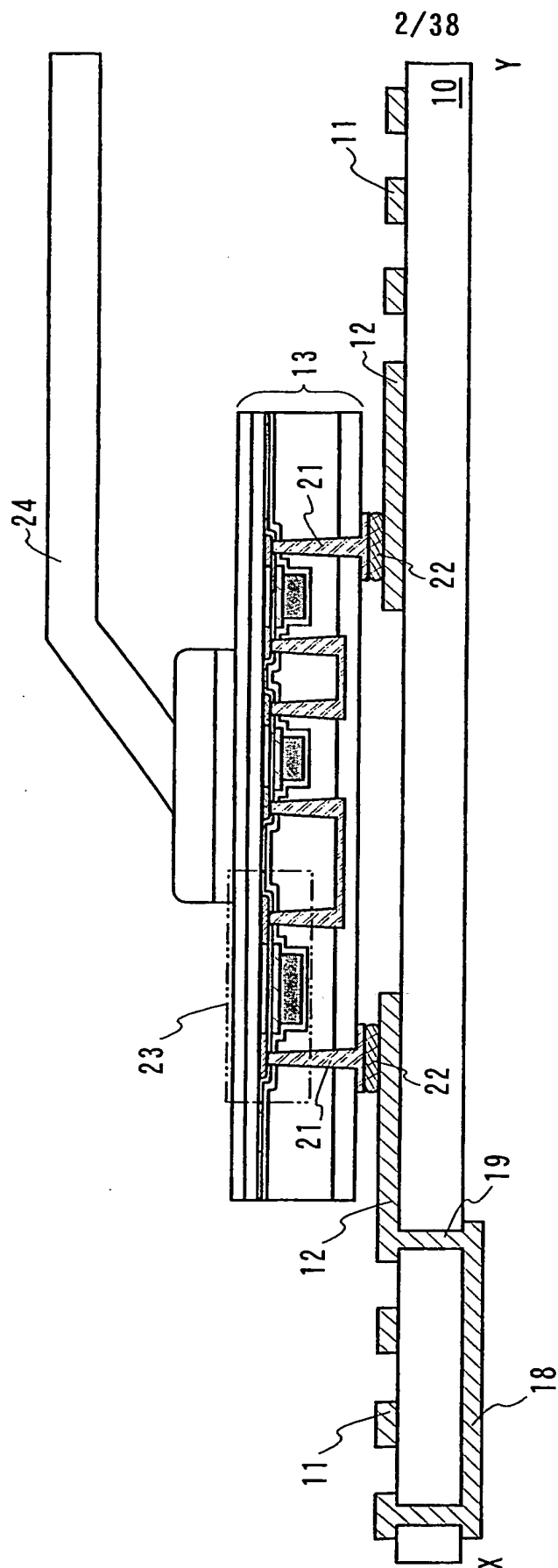


FIG. 2

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FIG. 3A

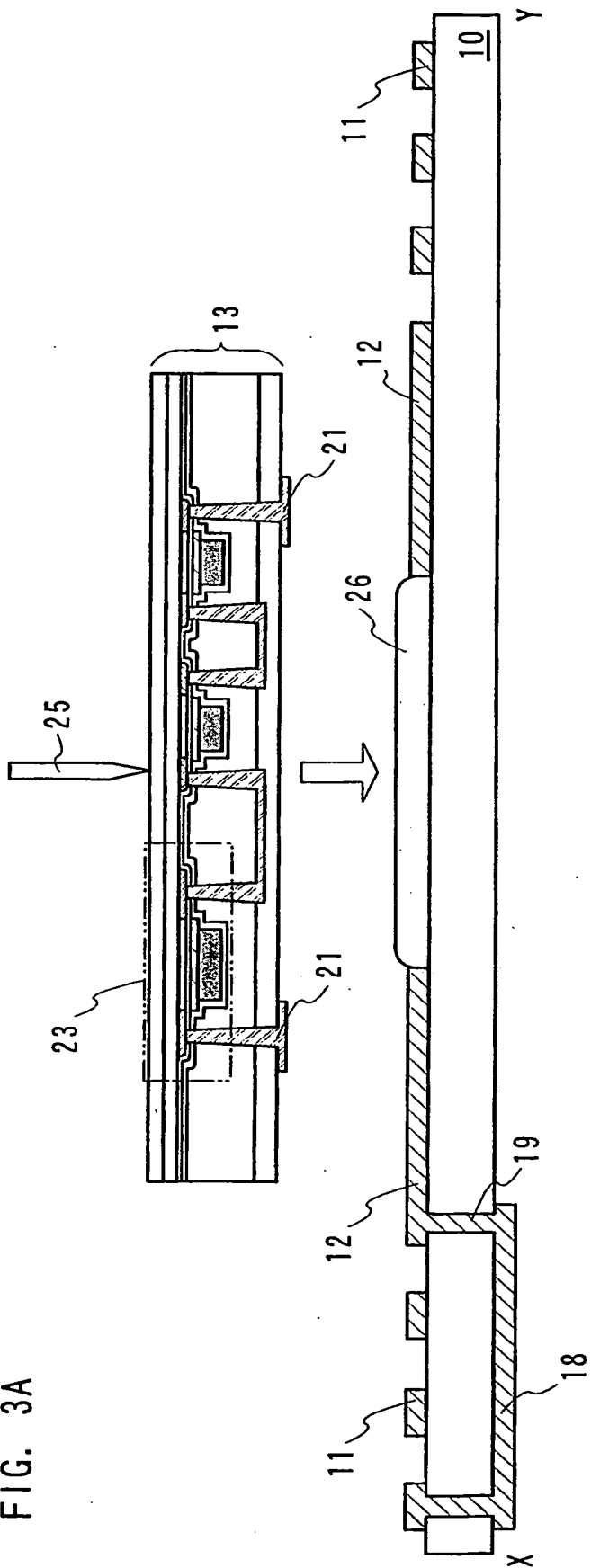
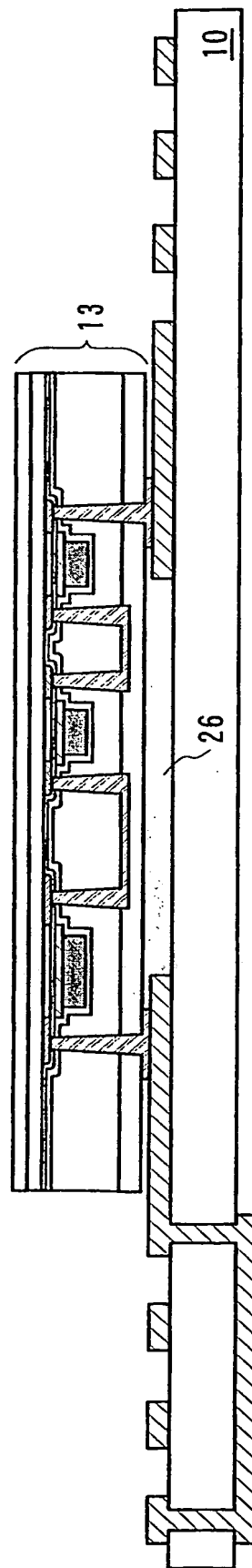


FIG. 3B



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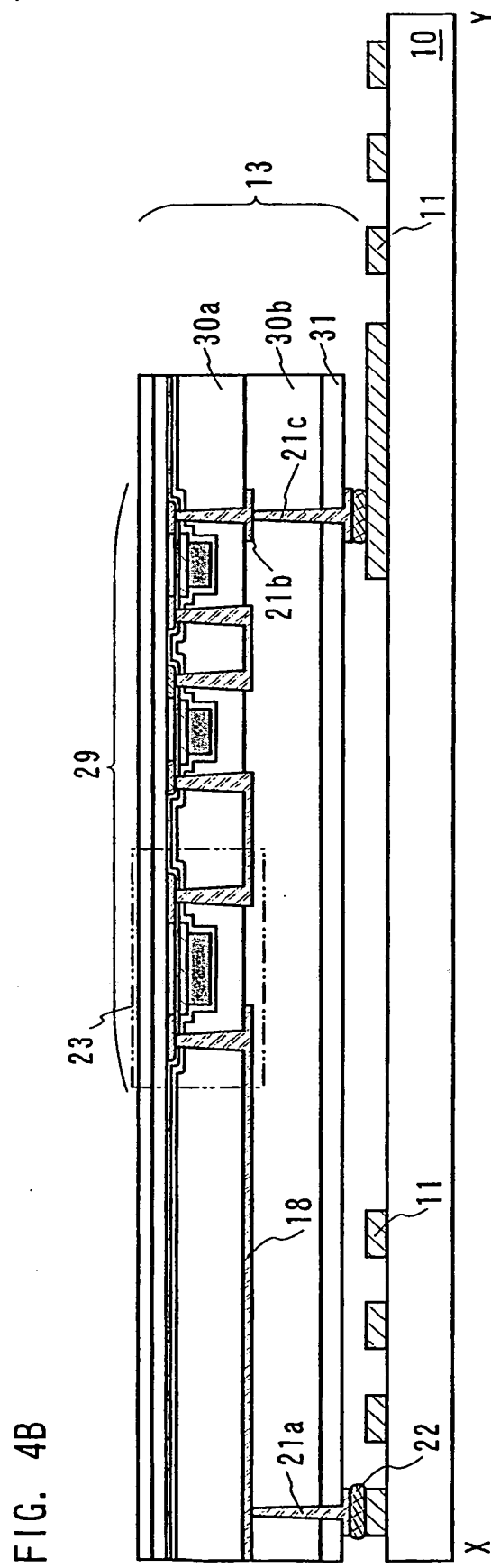
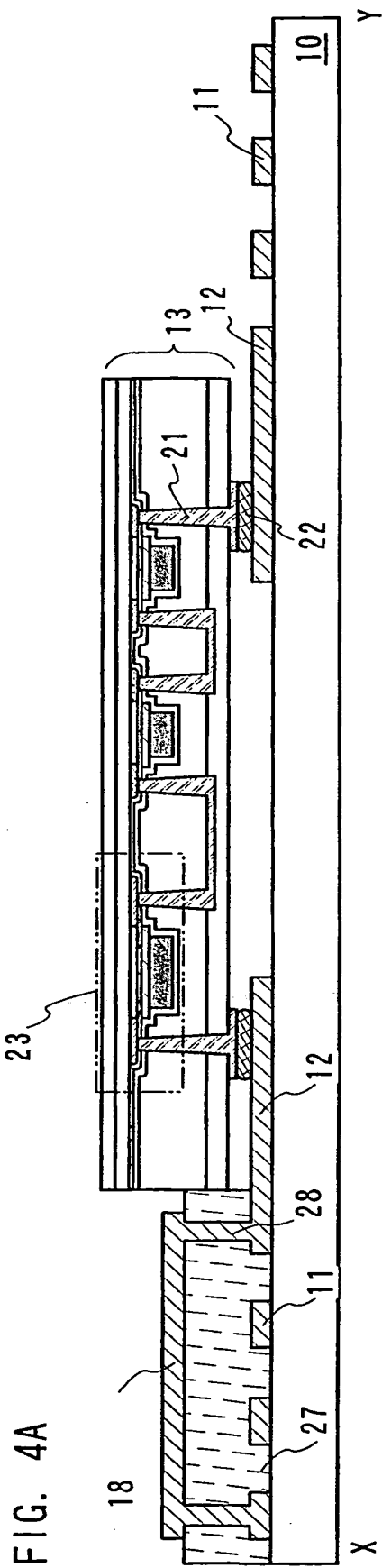


FIG. 5A

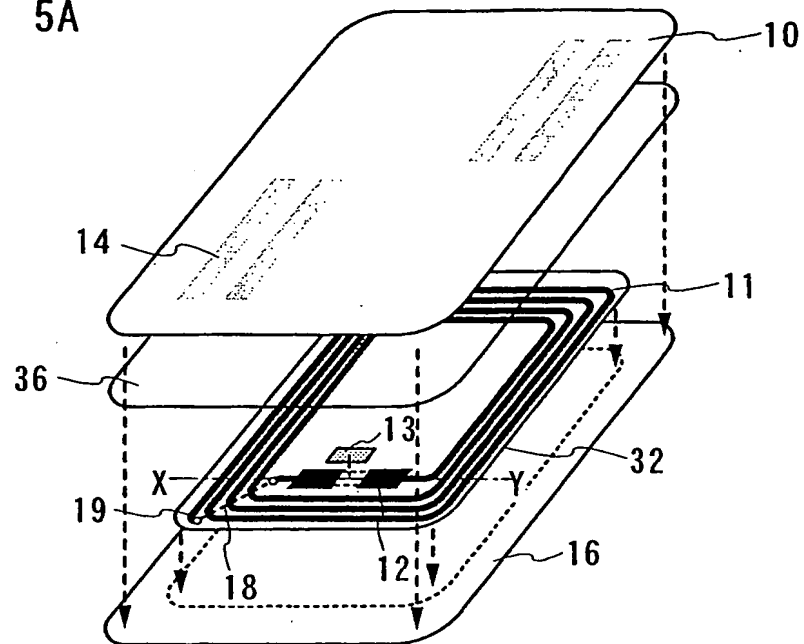
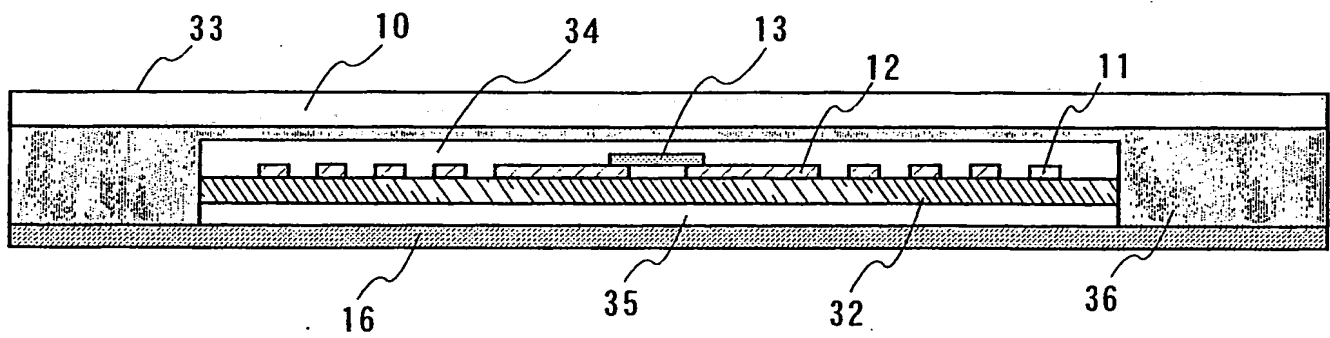


FIG. 5B



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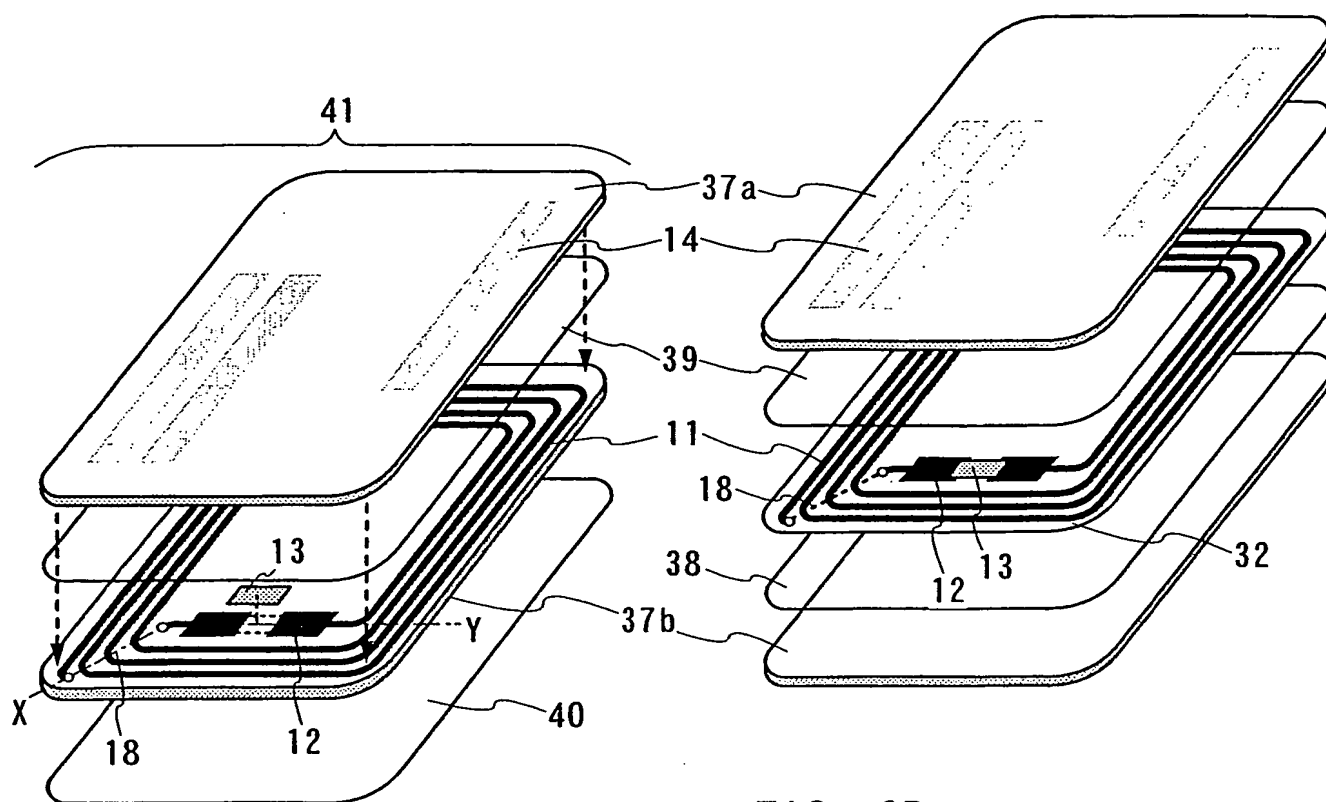


FIG. 6A

FIG. 6B

FIG. 7A

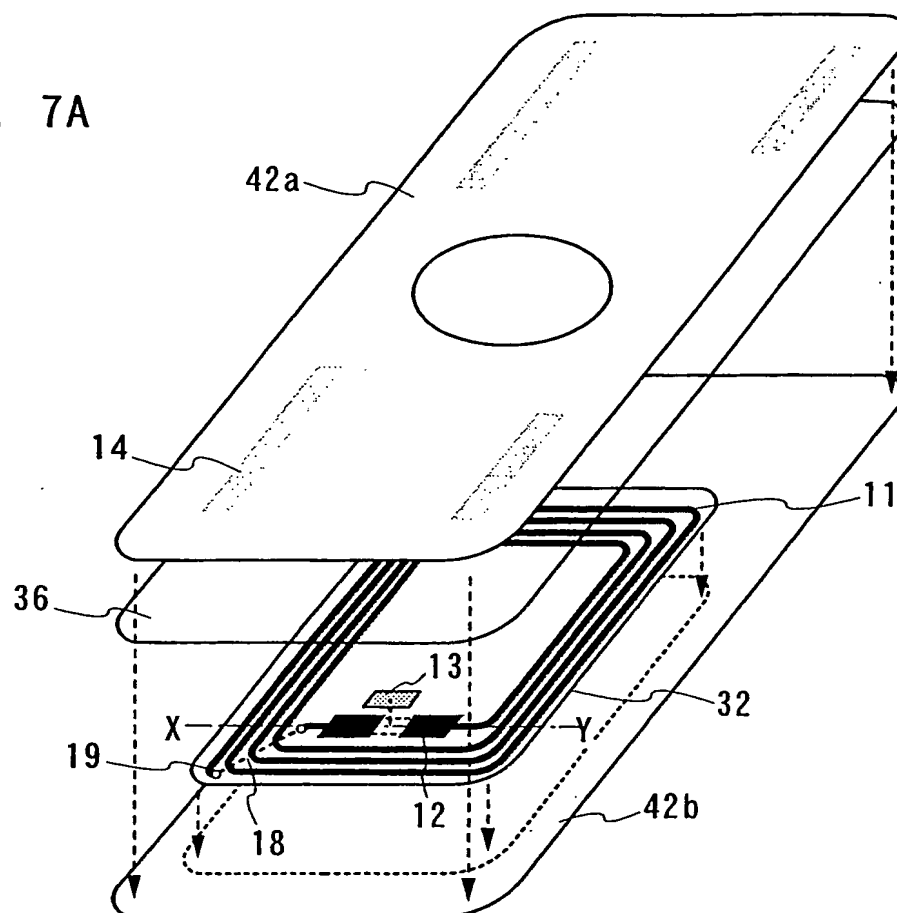
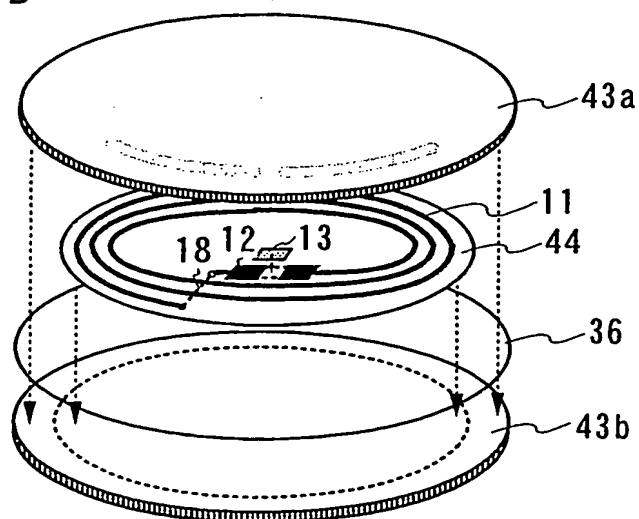
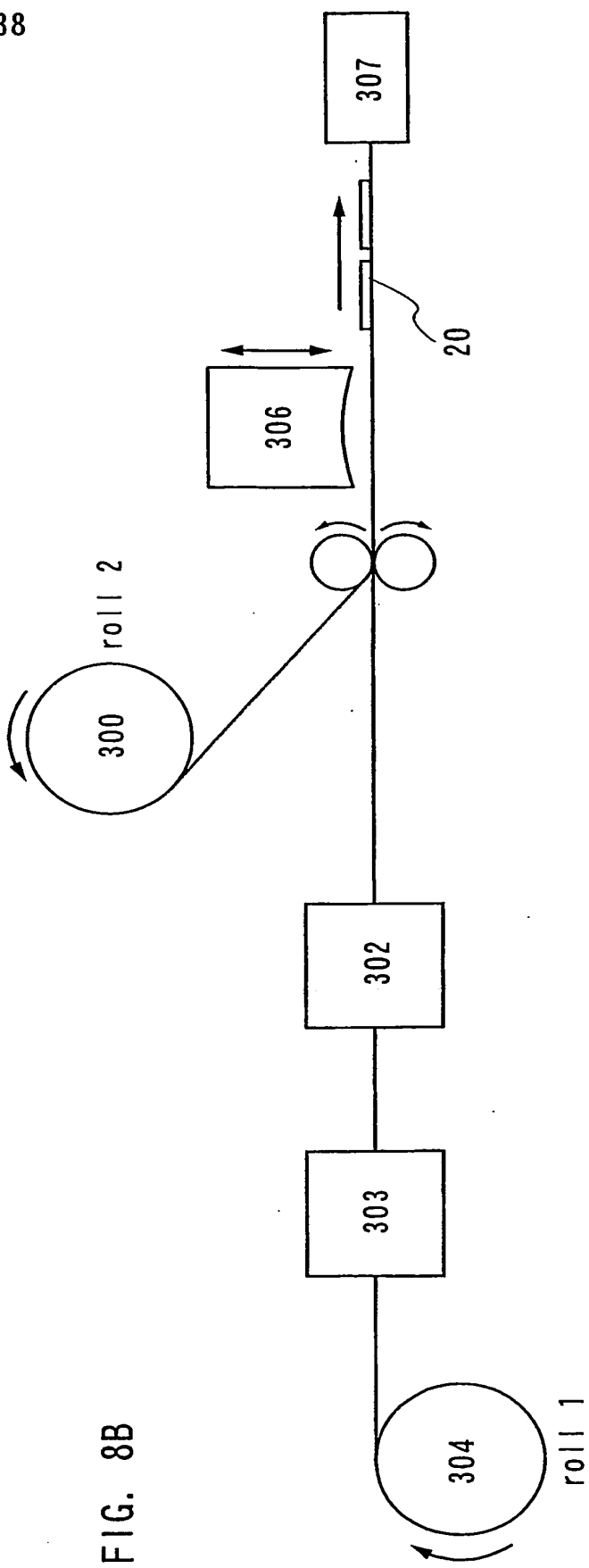
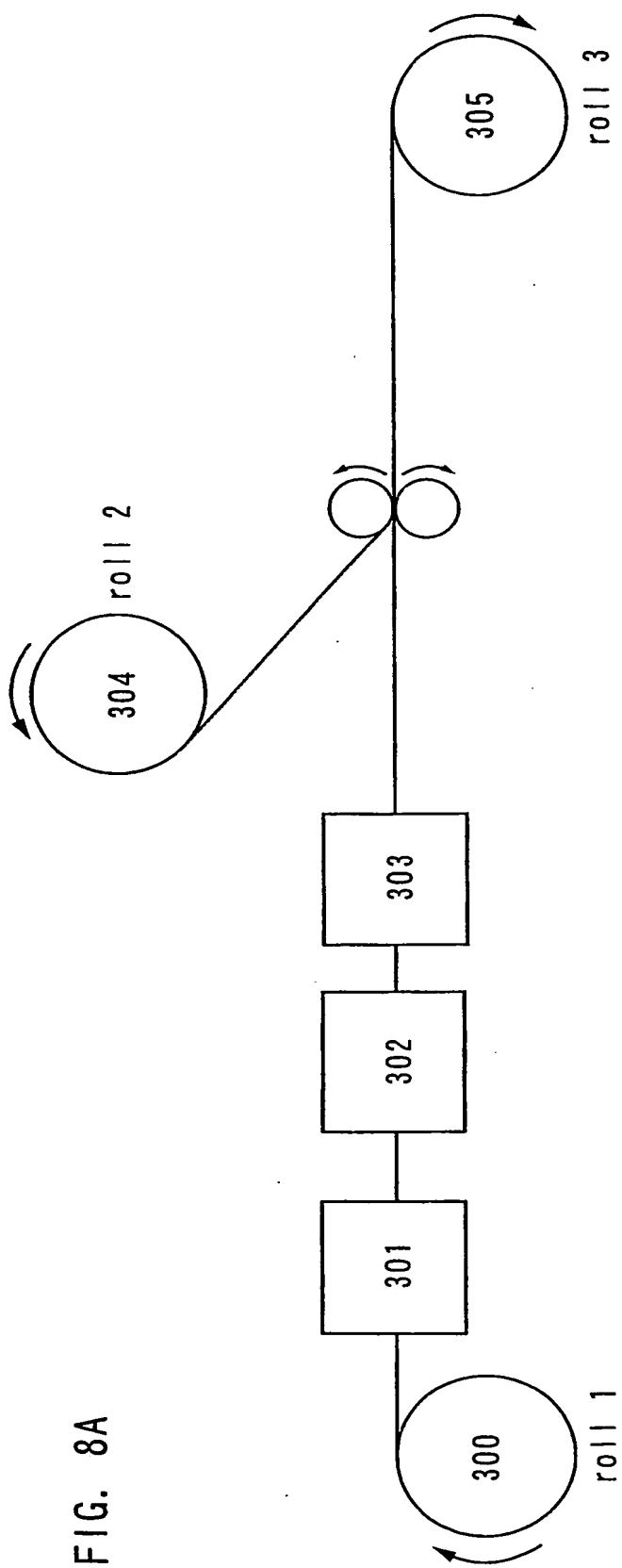


FIG. 7B



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FIG. 9A

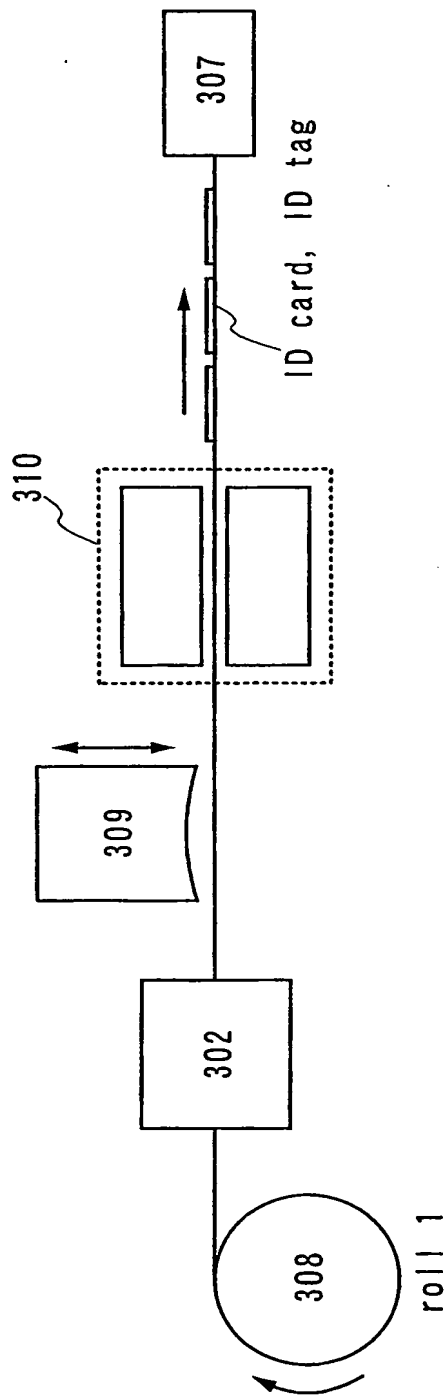


FIG. 9B

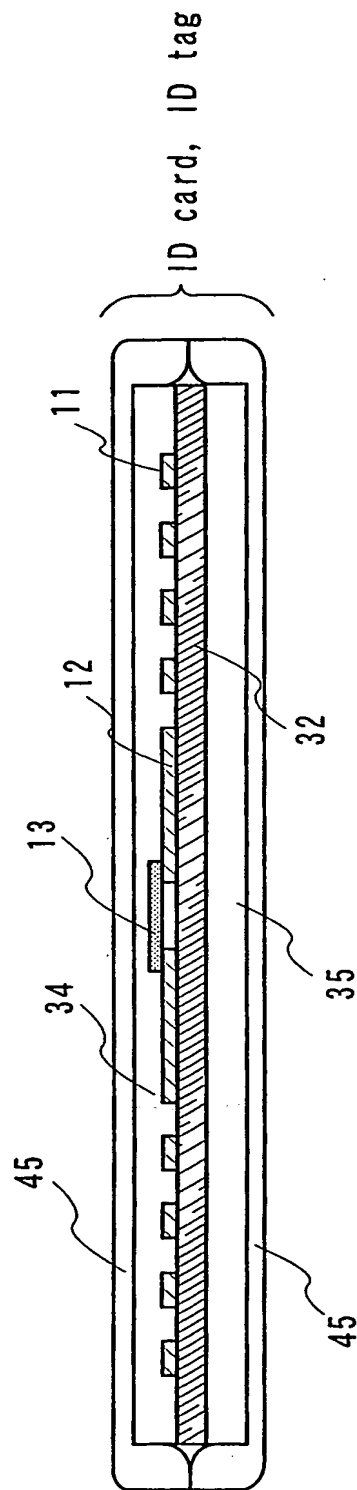


FIG. 10

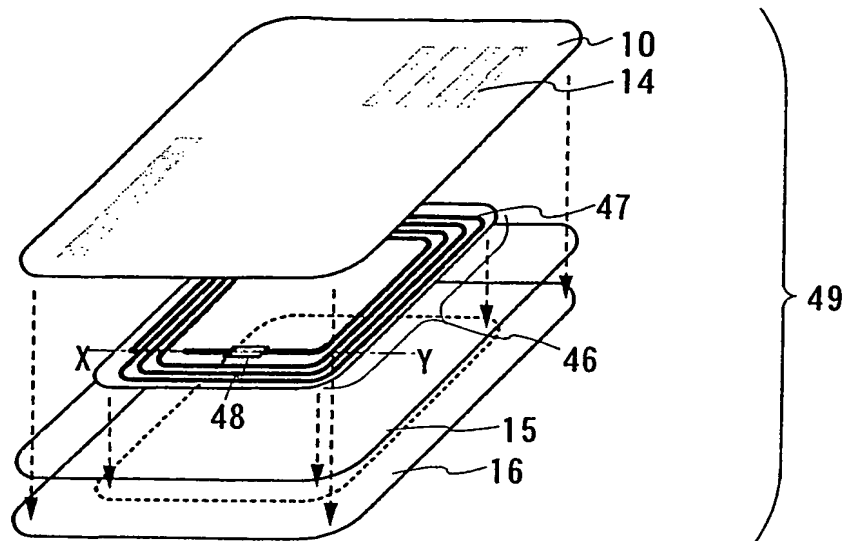
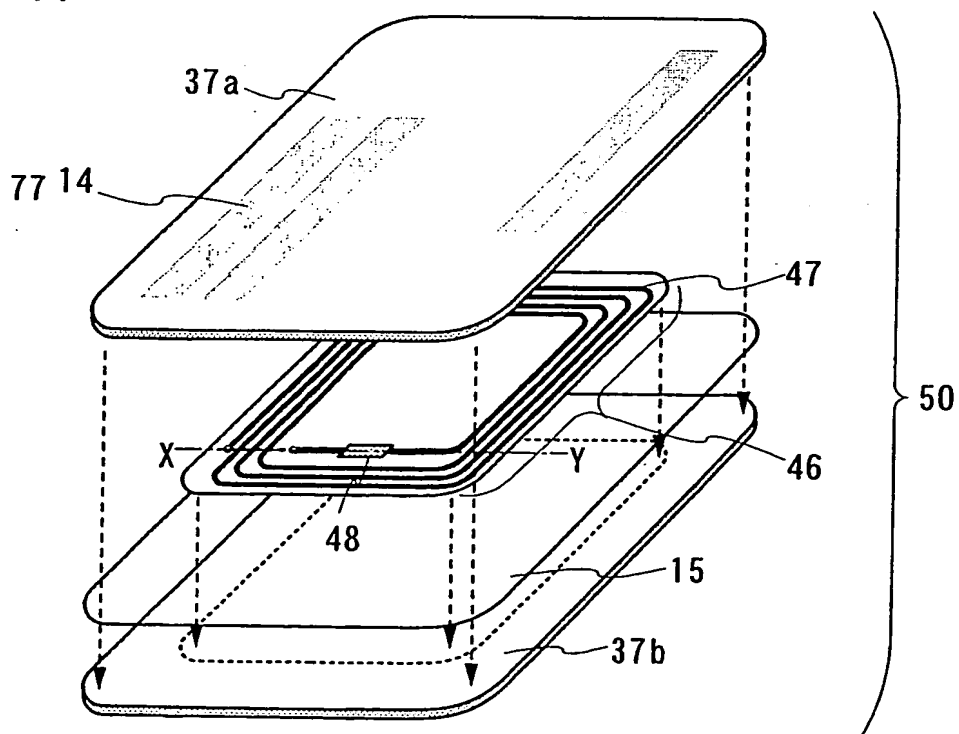


FIG. 11



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FIG. 12A

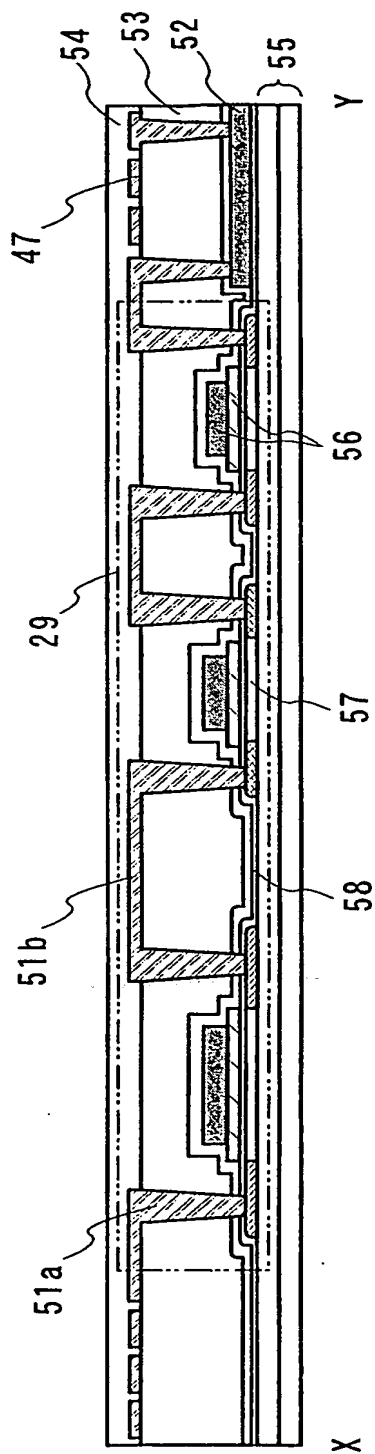


FIG. 12B

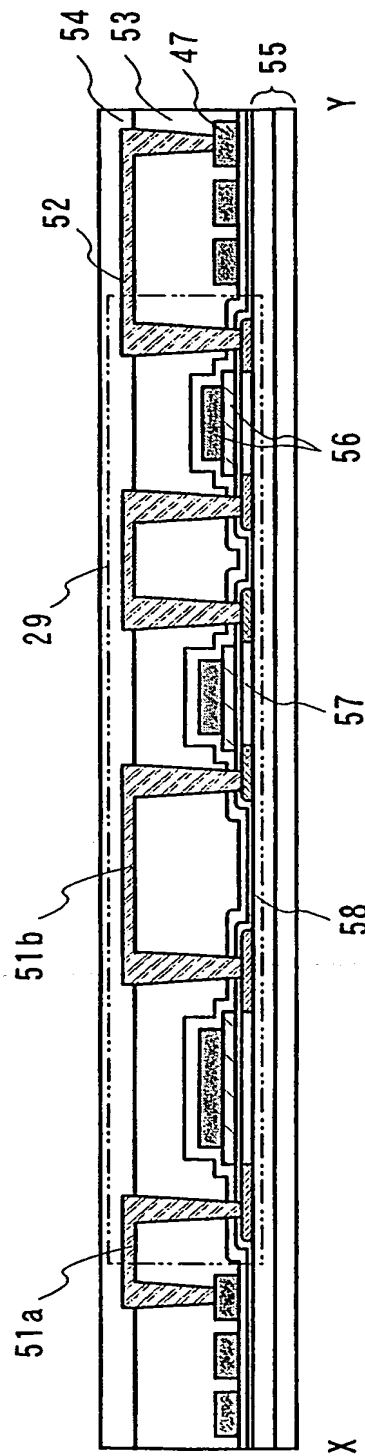


FIG. 13A

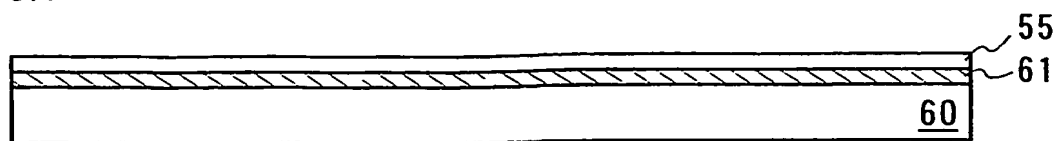


FIG. 13B

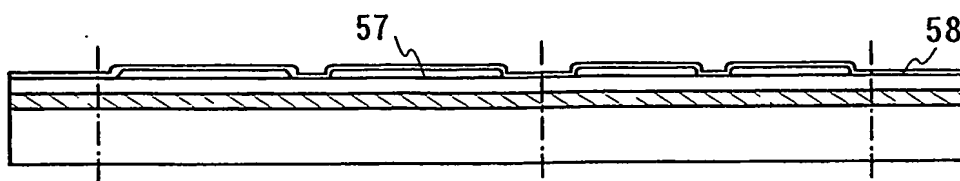


FIG. 13C

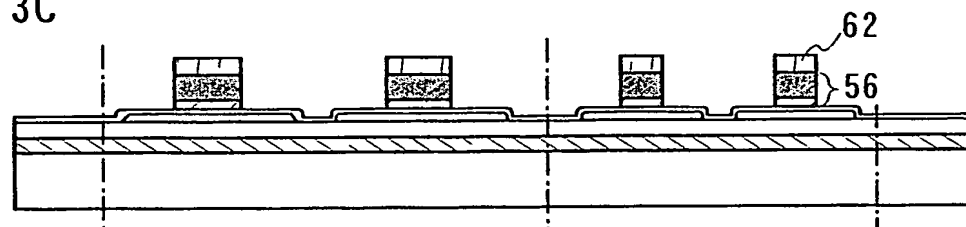


FIG. 13D

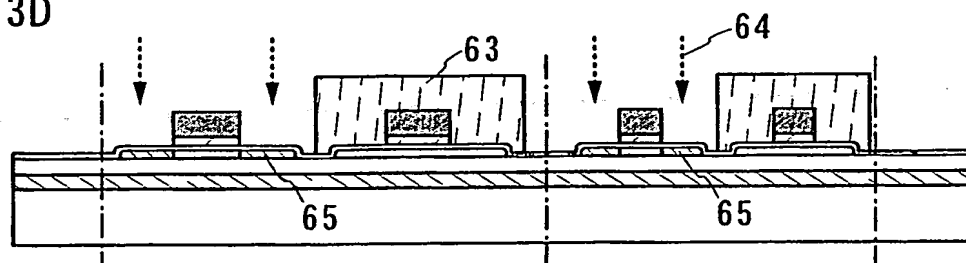


FIG. 13E

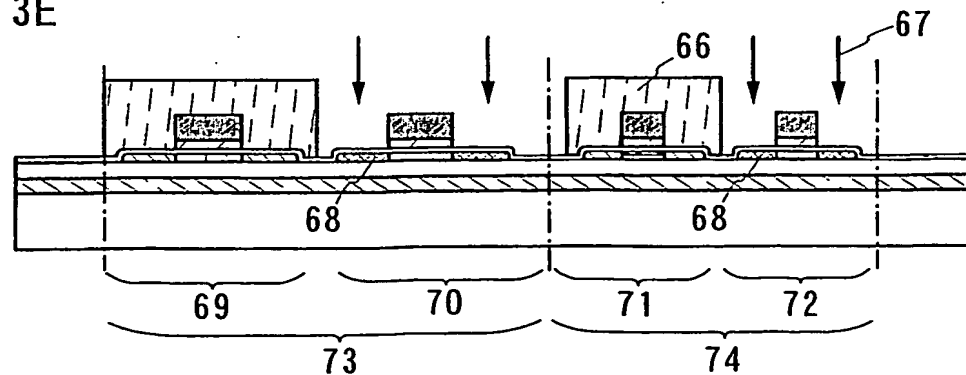


FIG. 14A

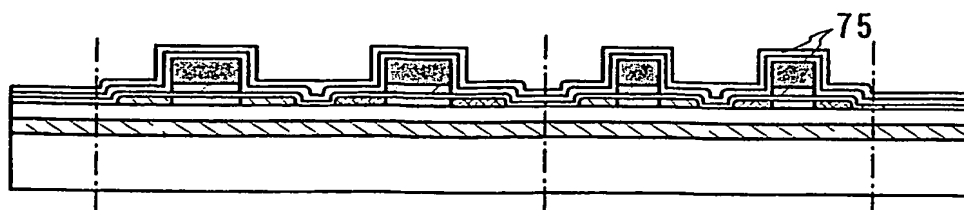


FIG. 14B

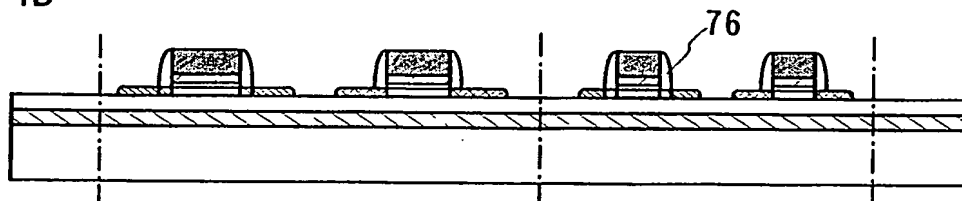


FIG. 14C

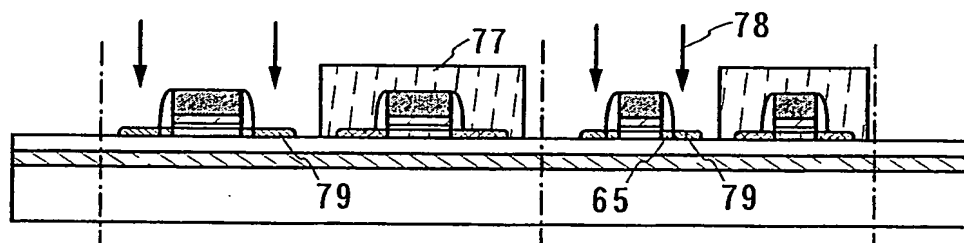
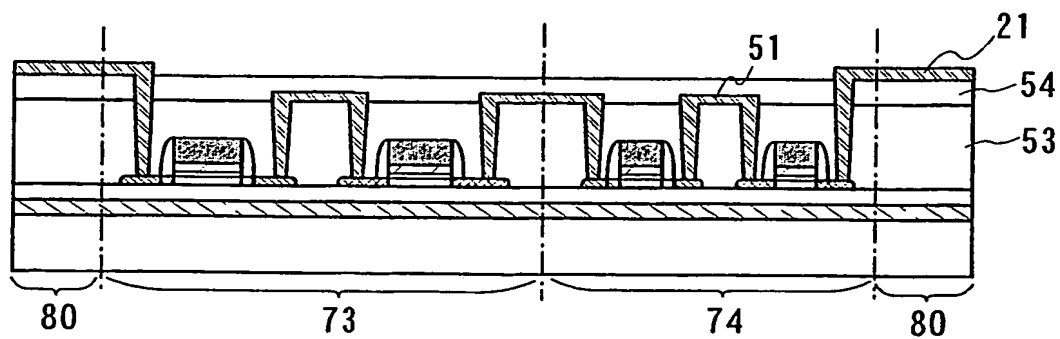


FIG. 14D



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FIG. 15A

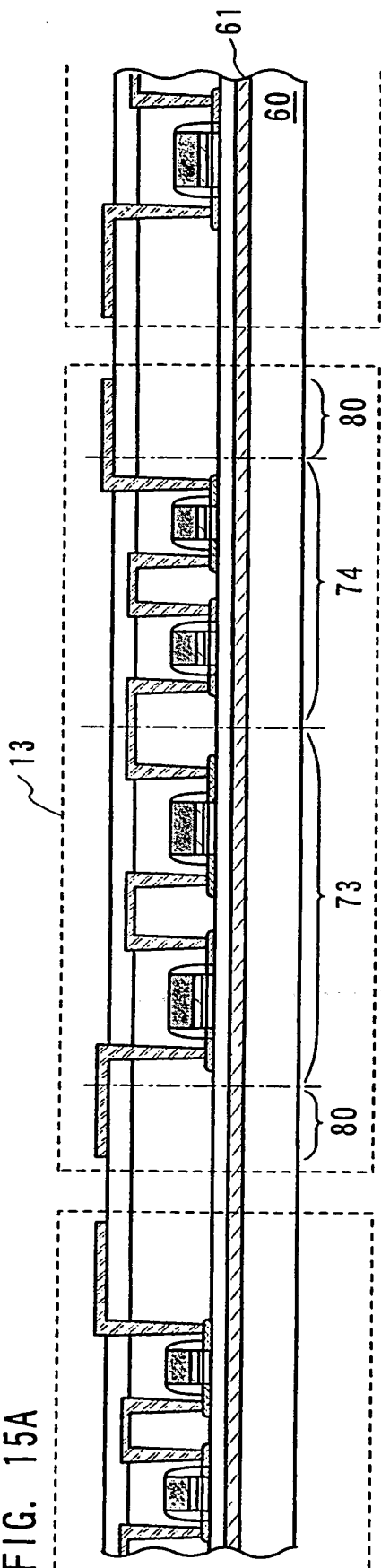


FIG. 15B

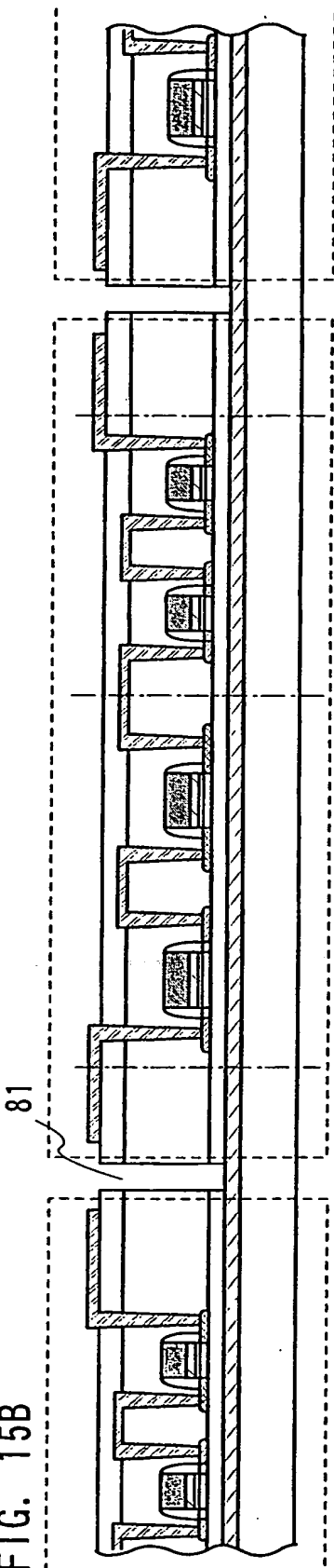


FIG. 15C

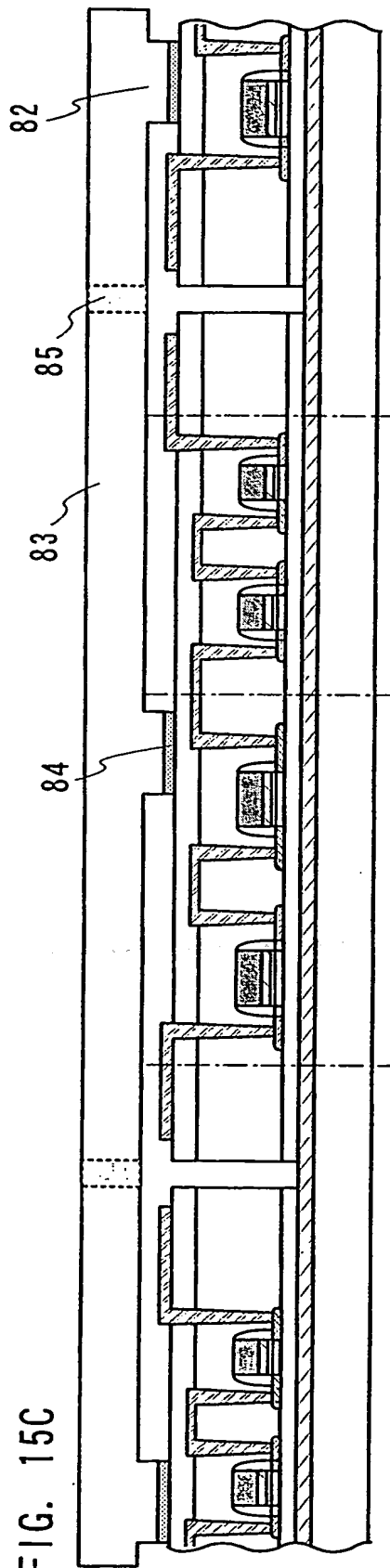


FIG. 16A

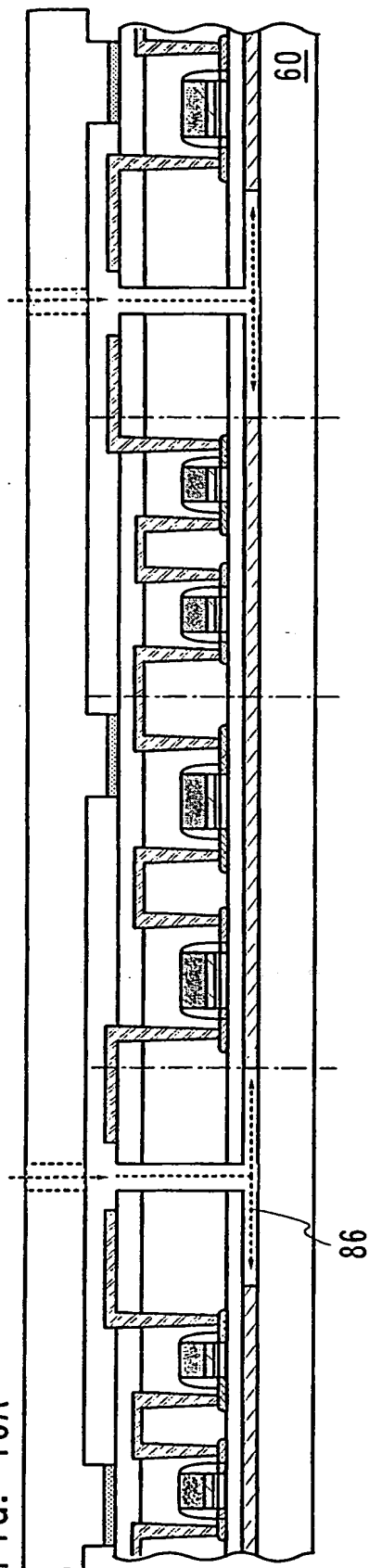


FIG. 16B

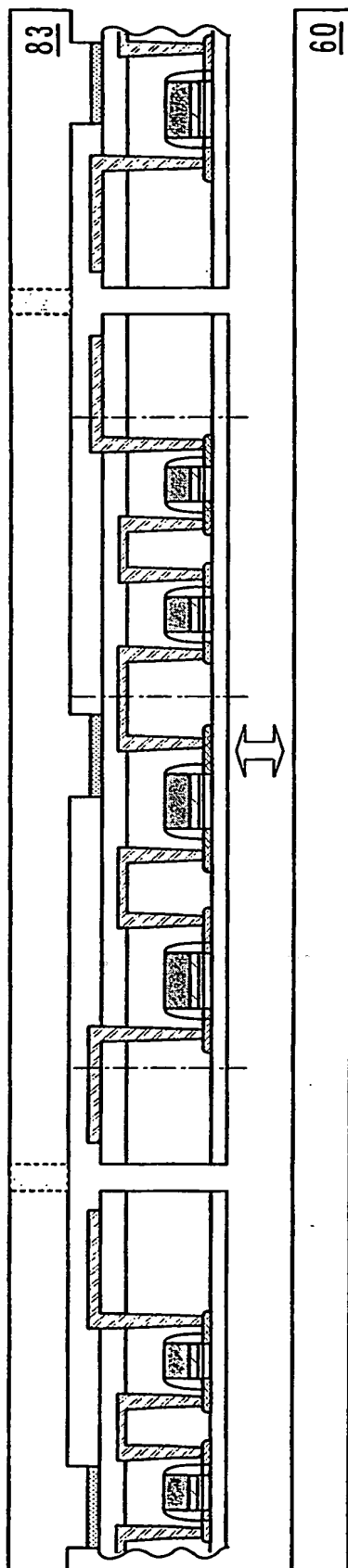
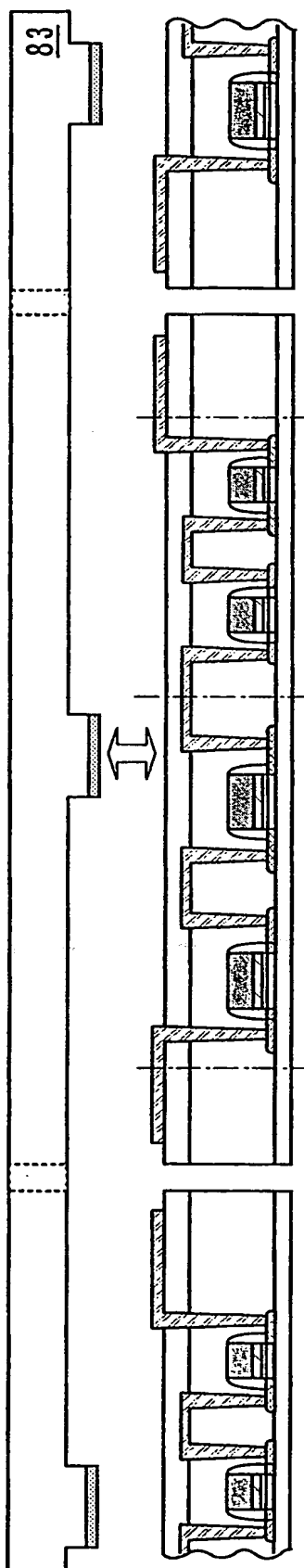


FIG. 16C



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FIG. 17A

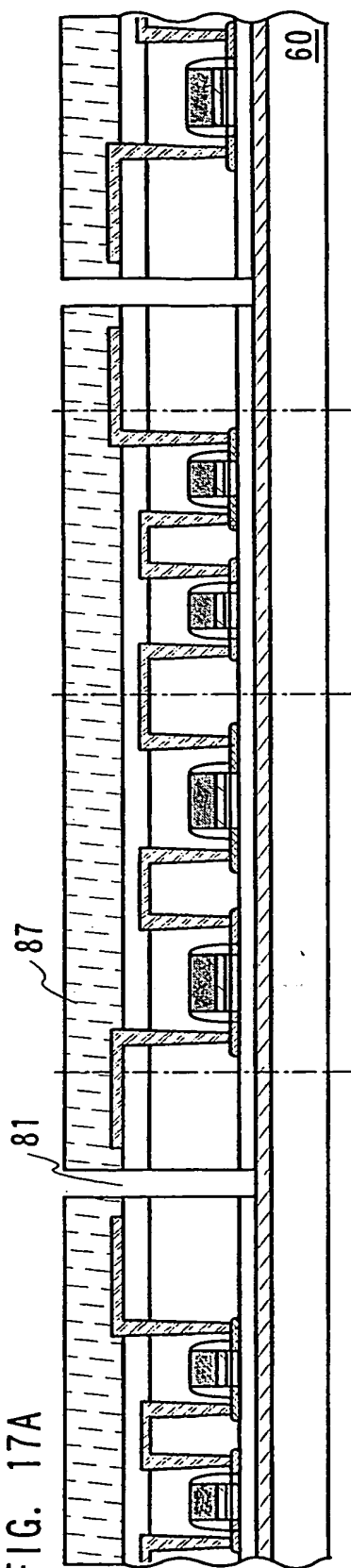


FIG. 17B

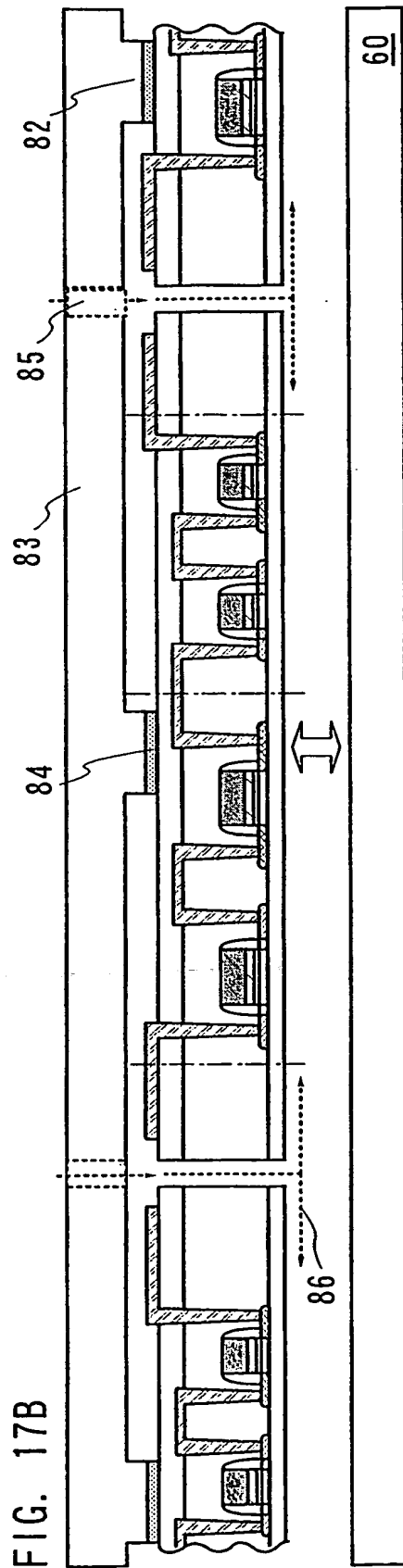
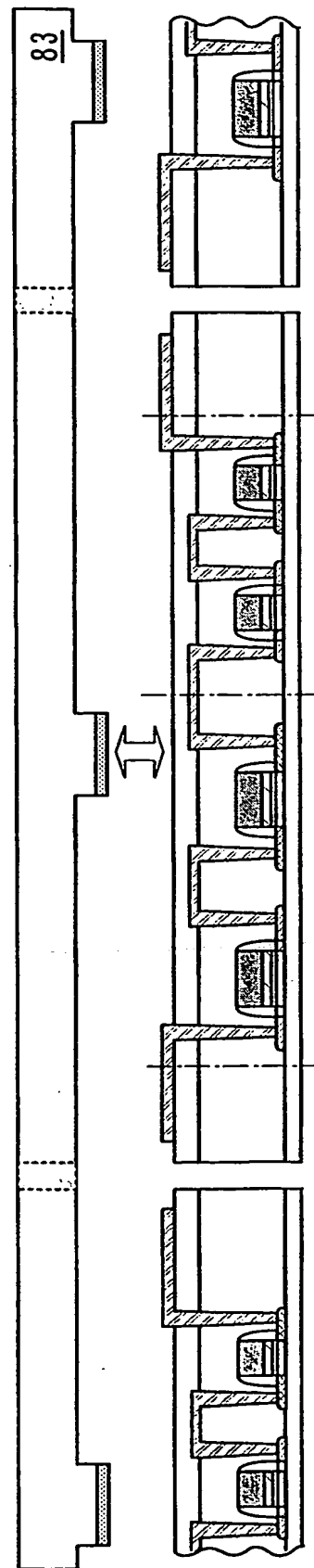


FIG. 17C



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FIG. 18A

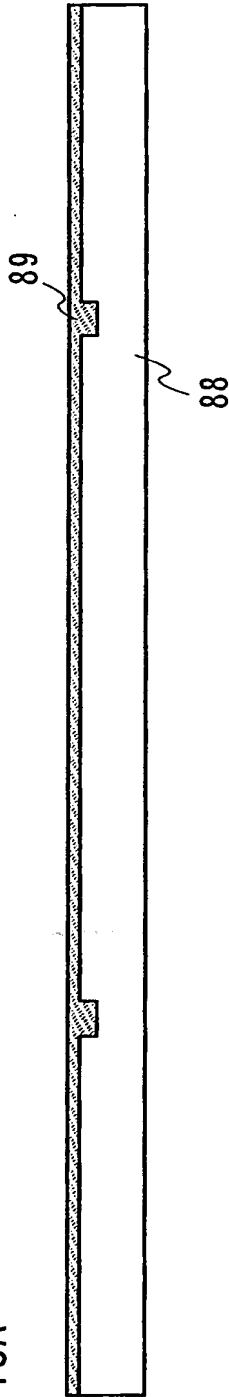


FIG. 18B

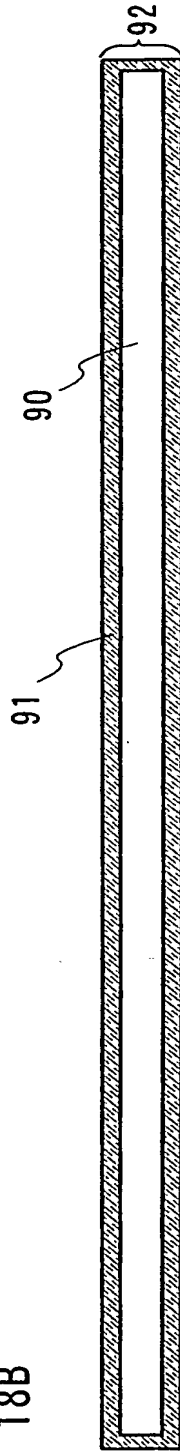
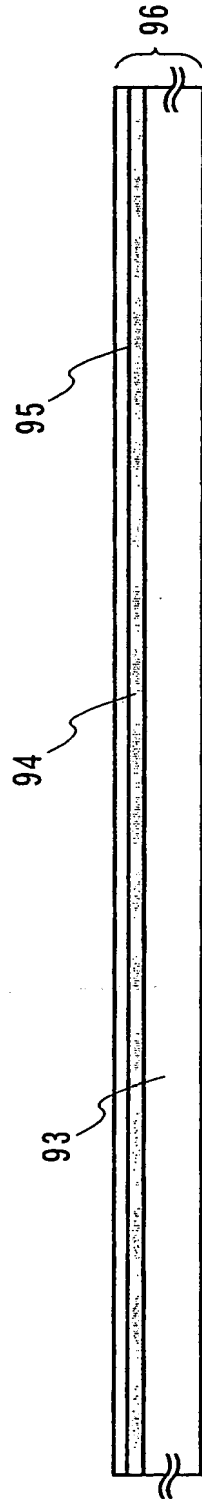


FIG. 18C



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FIG. 19A

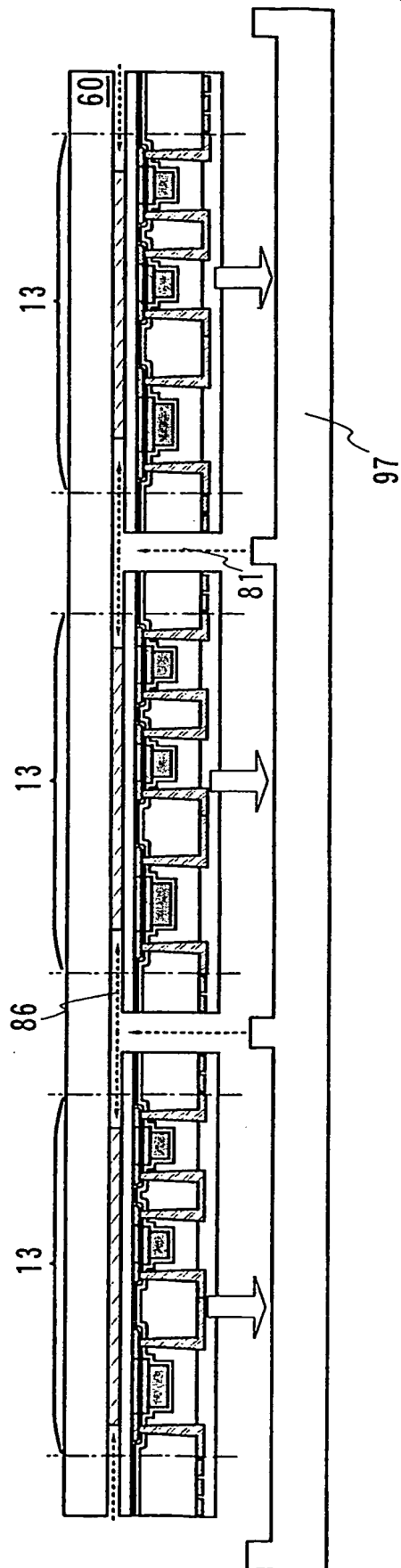


FIG. 19B

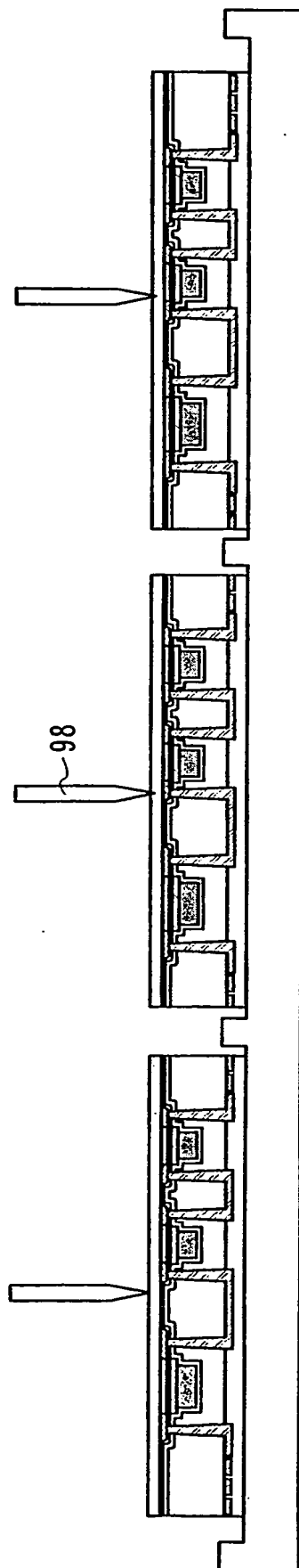
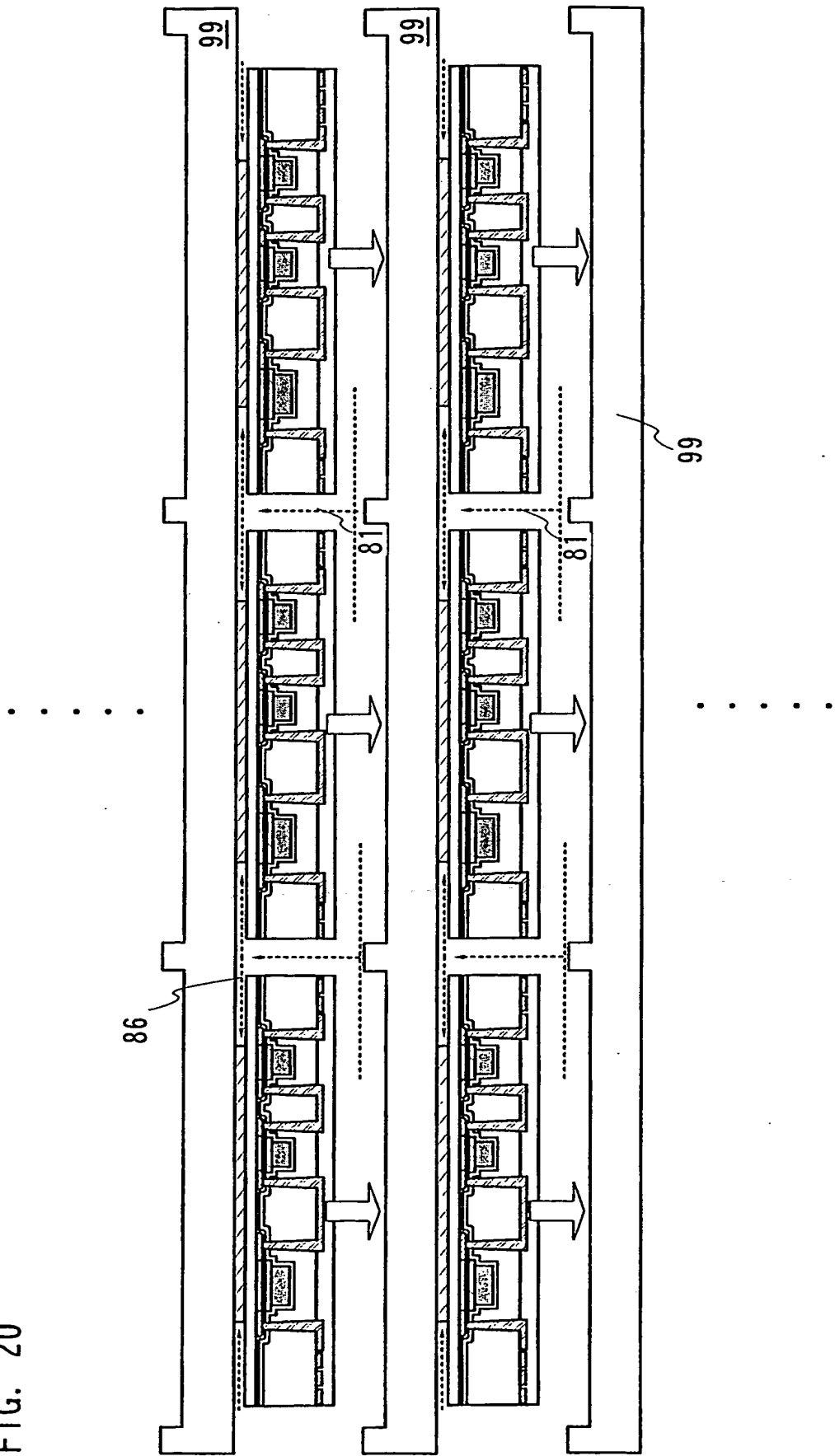
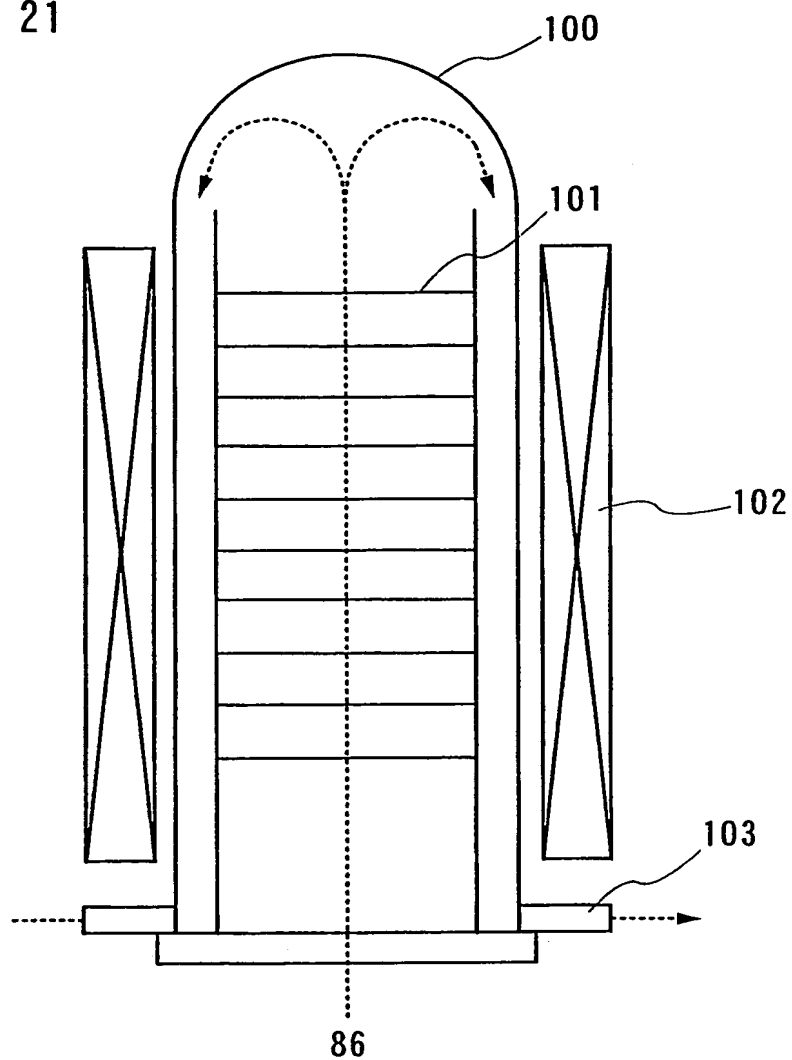


FIG. 20



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FIG. 21



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FIG. 22A

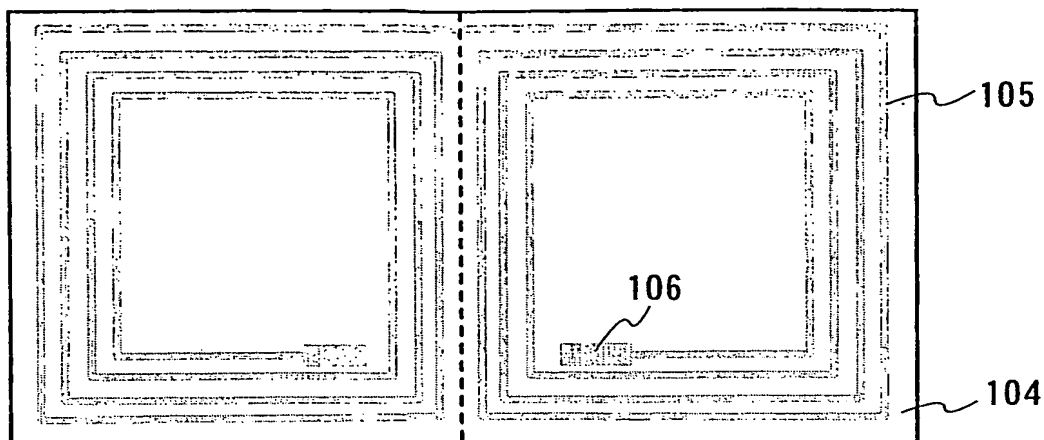


FIG. 22B

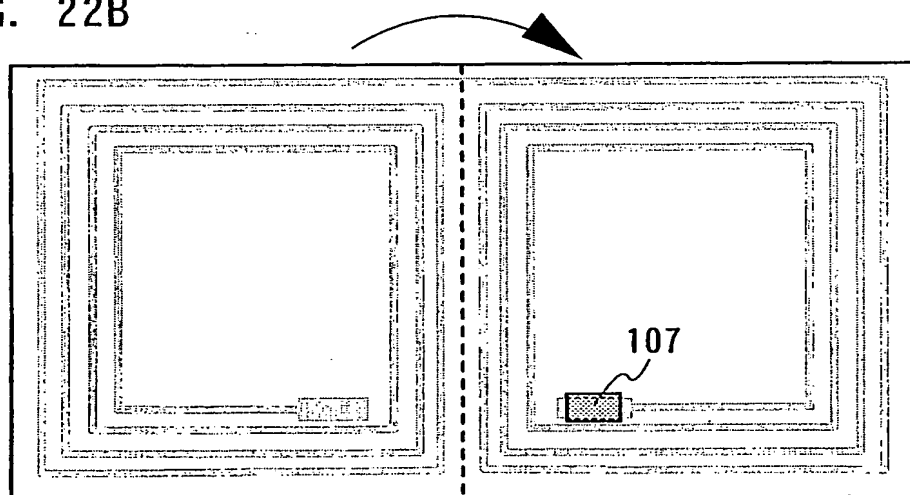
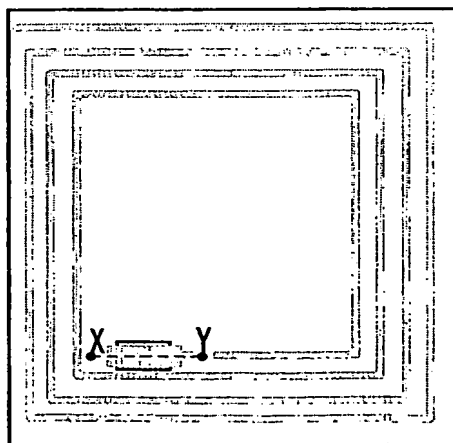


FIG. 22C



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FIG. 23A

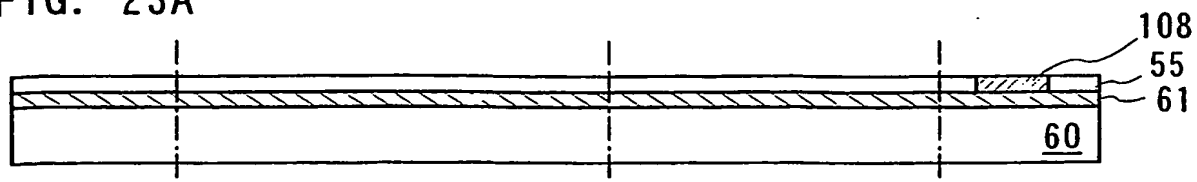


FIG. 23B

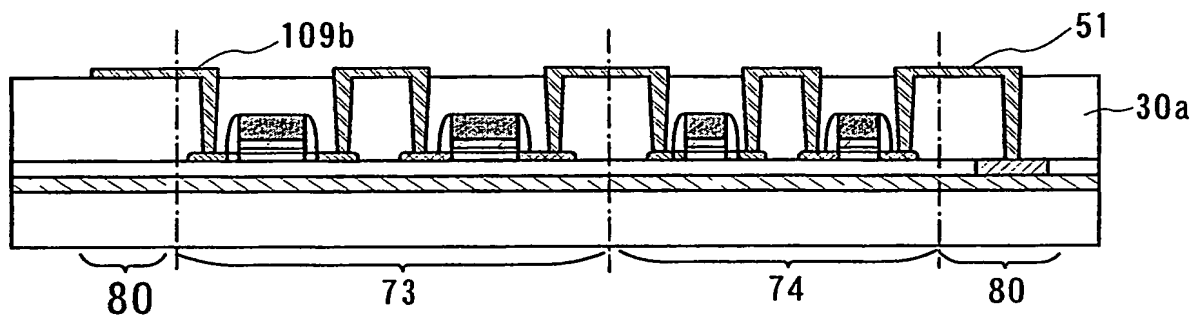


FIG. 23C

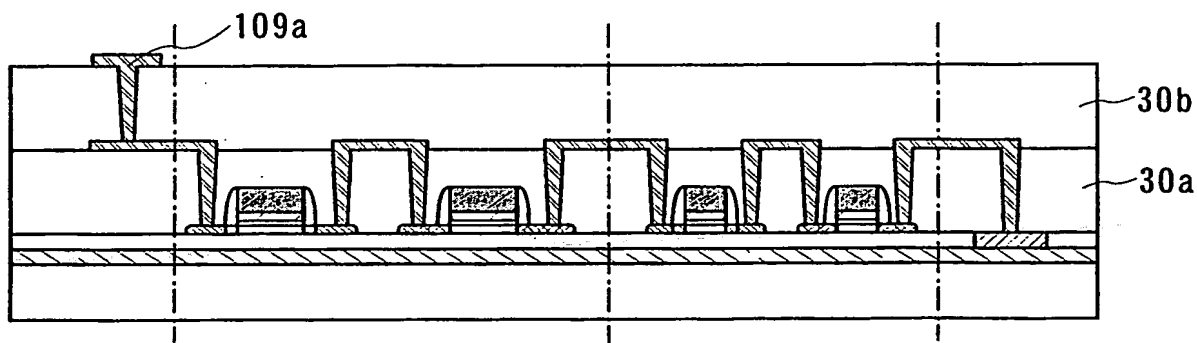
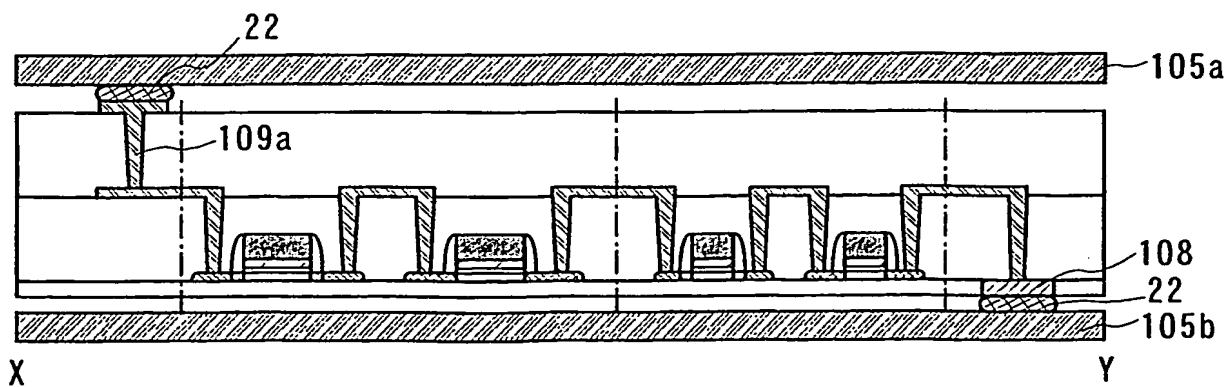


FIG. 23D



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FIG. 24A

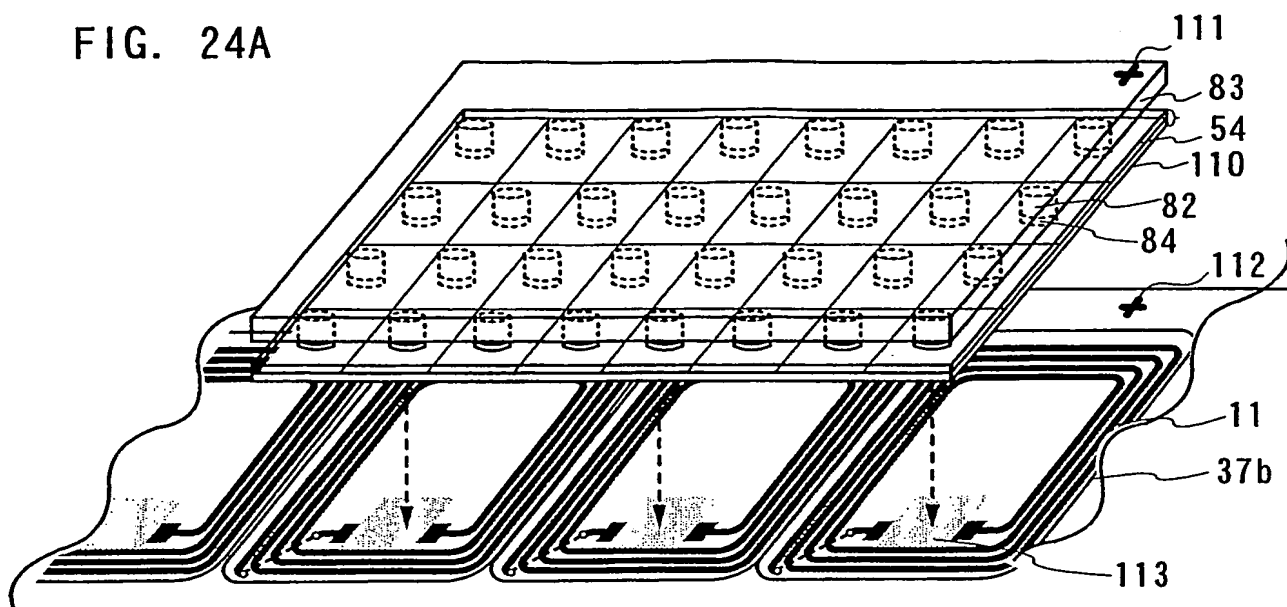


FIG. 24B

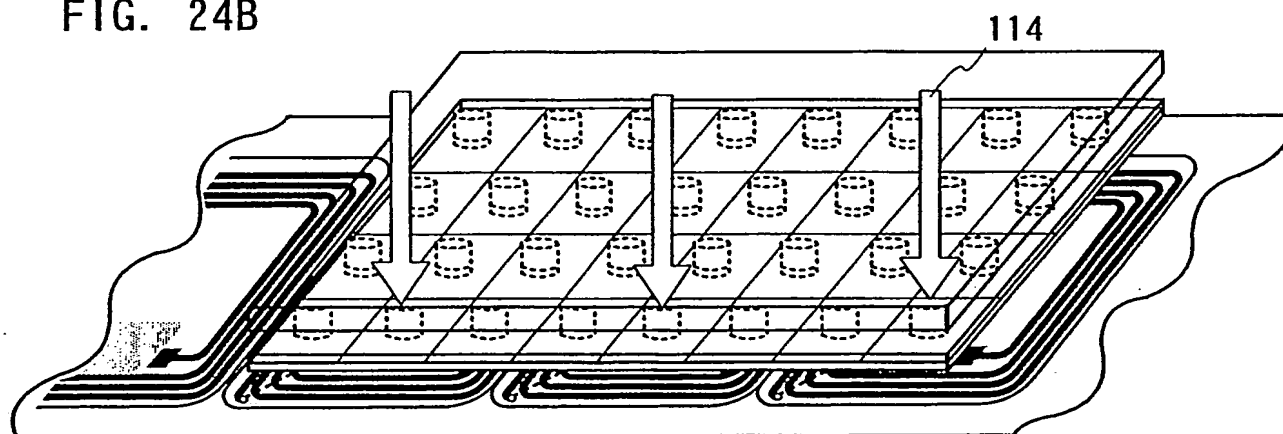


FIG. 24C

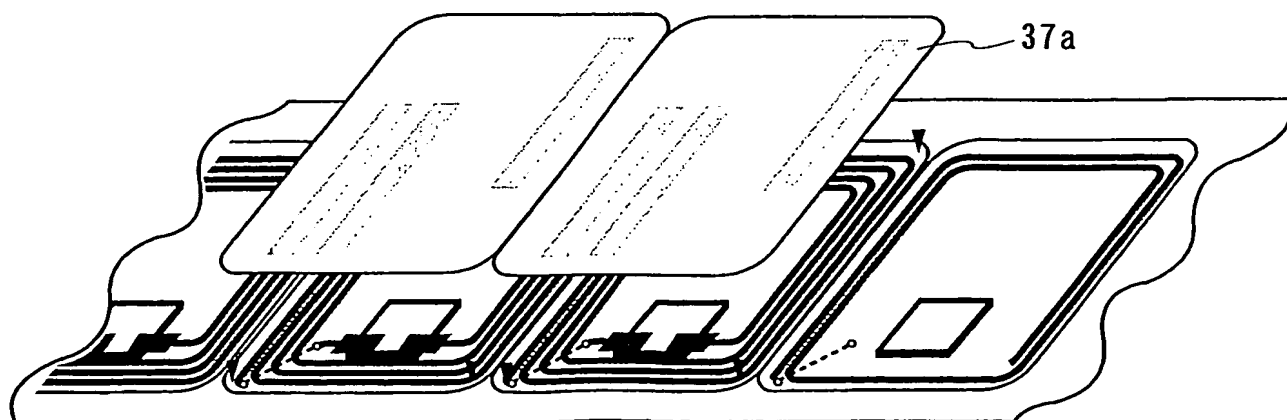


FIG. 25A

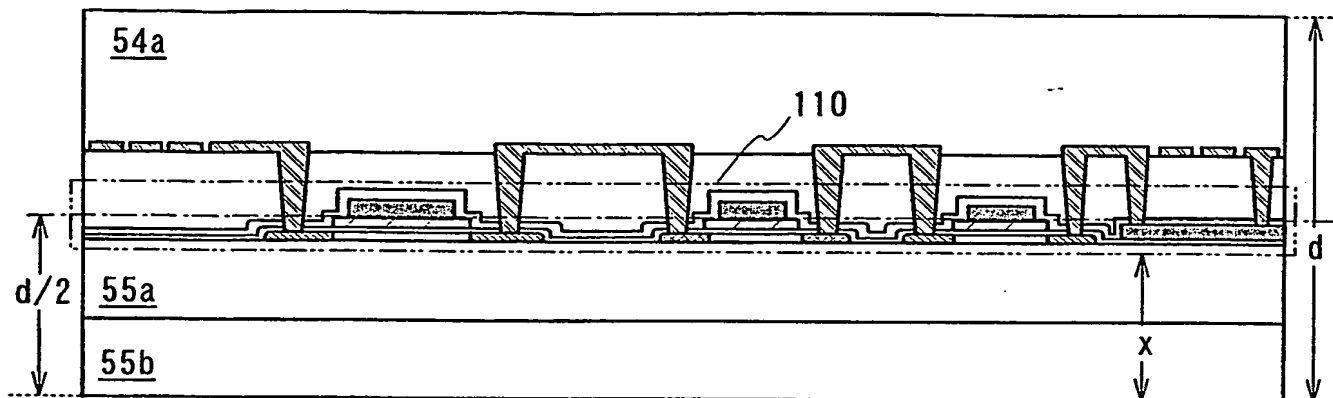


FIG. 25B

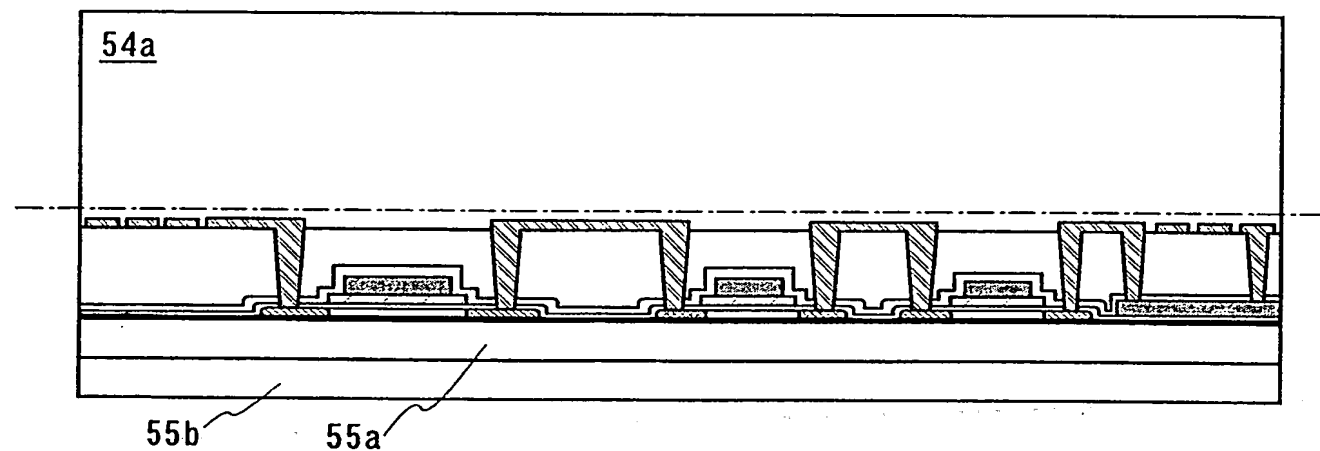
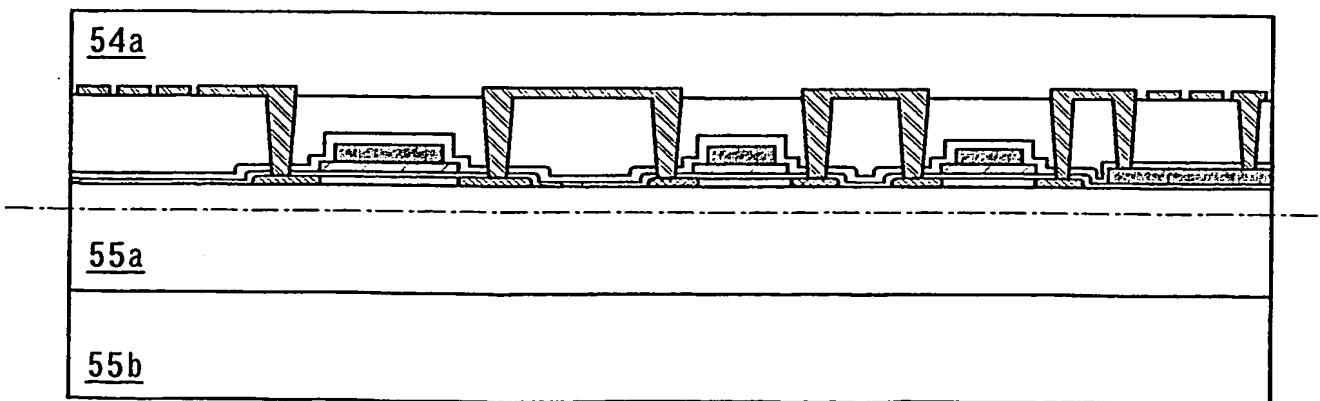
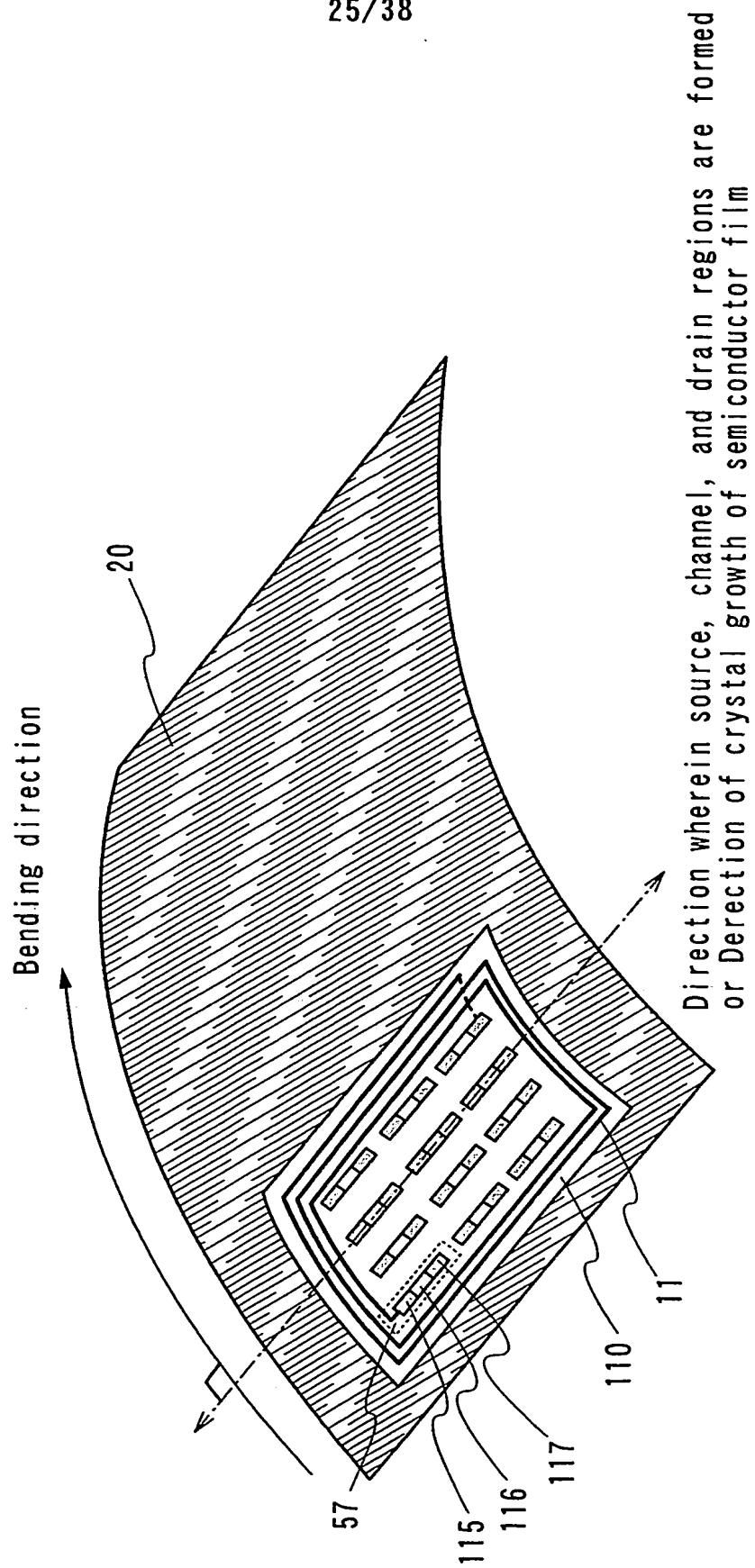


FIG. 25C



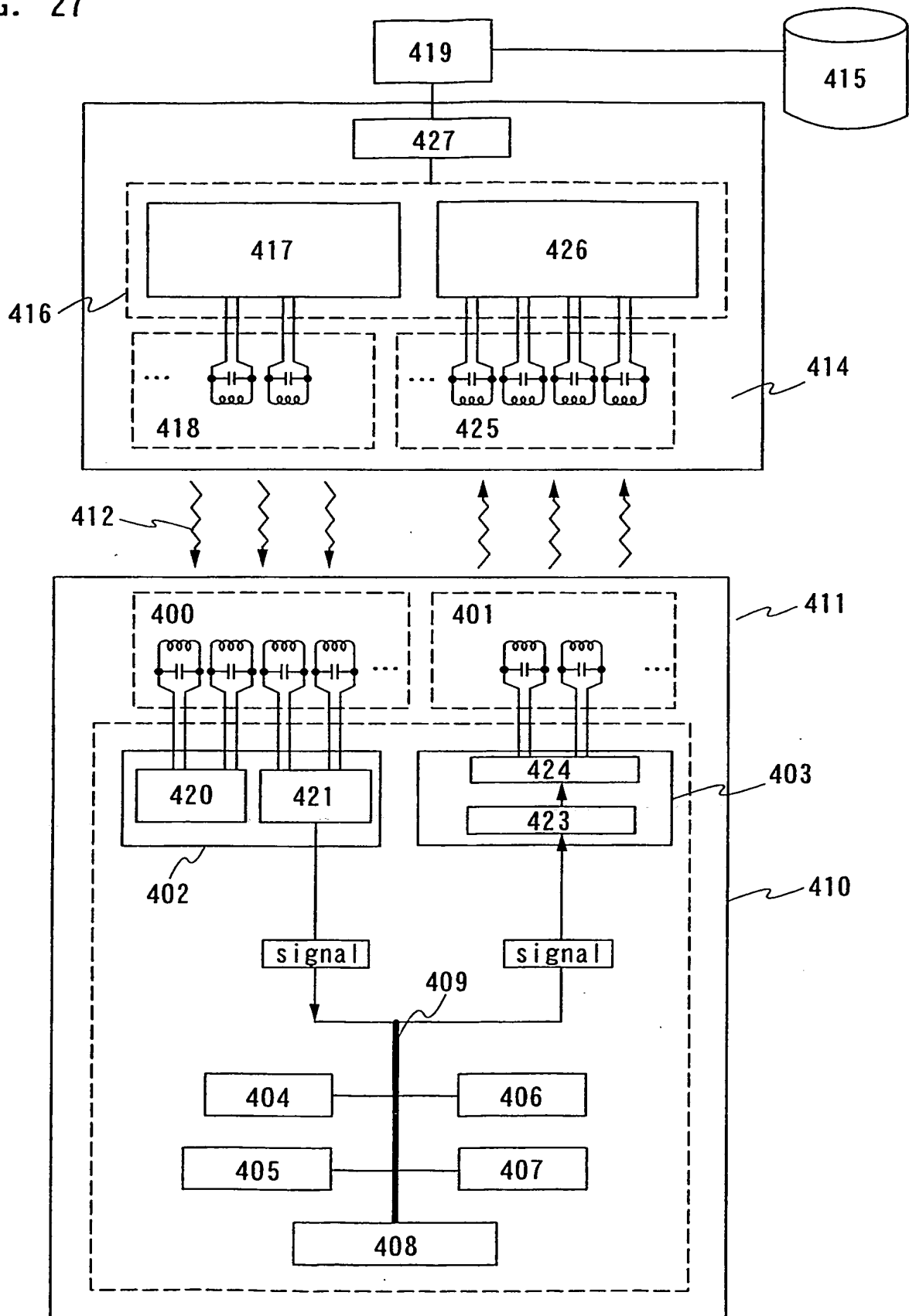
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FIG. 26



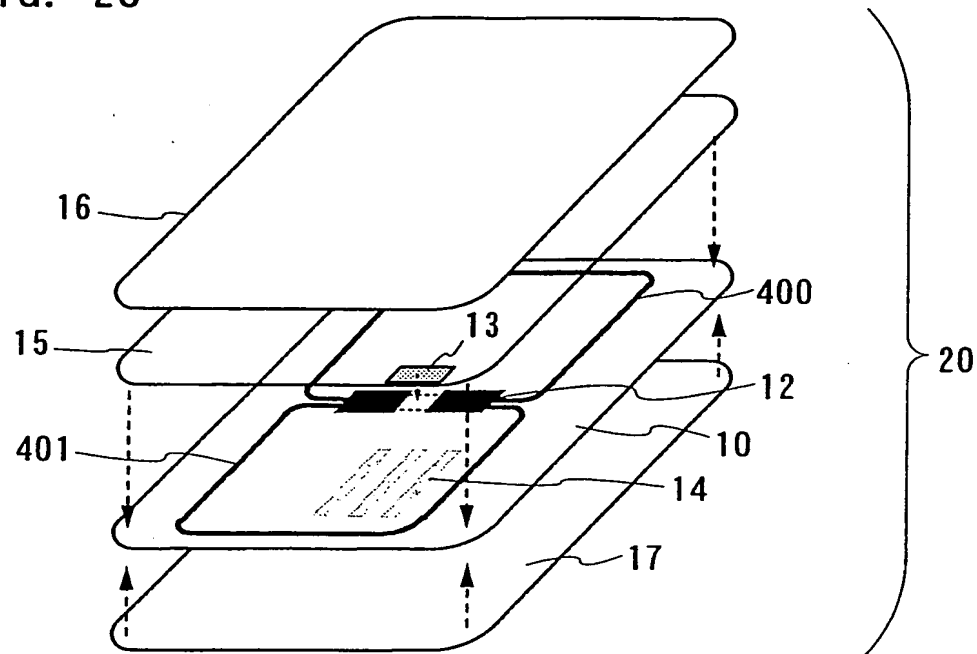
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FIG. 27



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FIG. 28



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FIG. 29

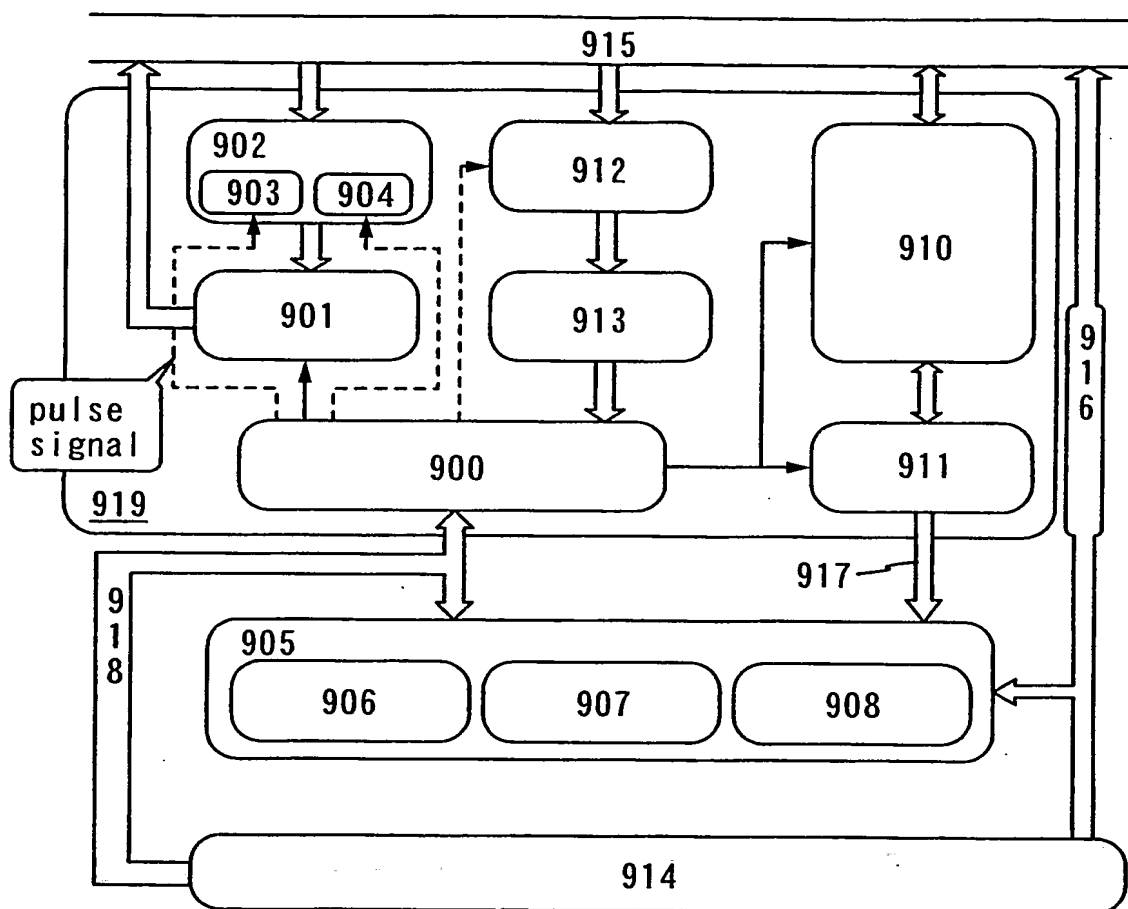


FIG. 30A

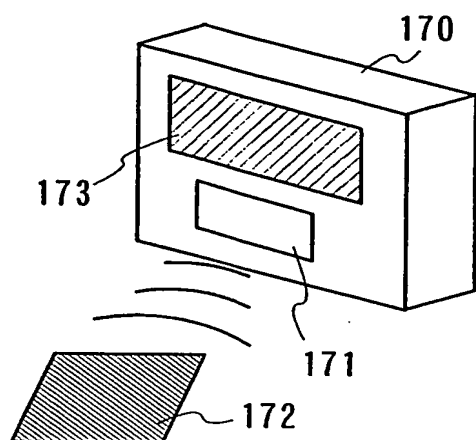


FIG. 30B

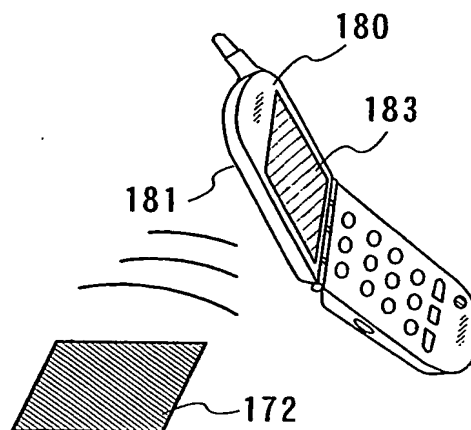
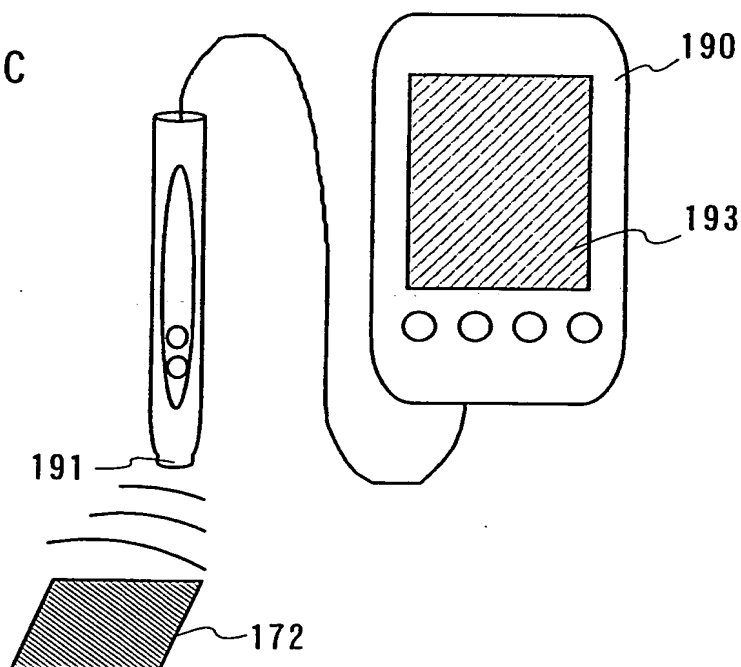
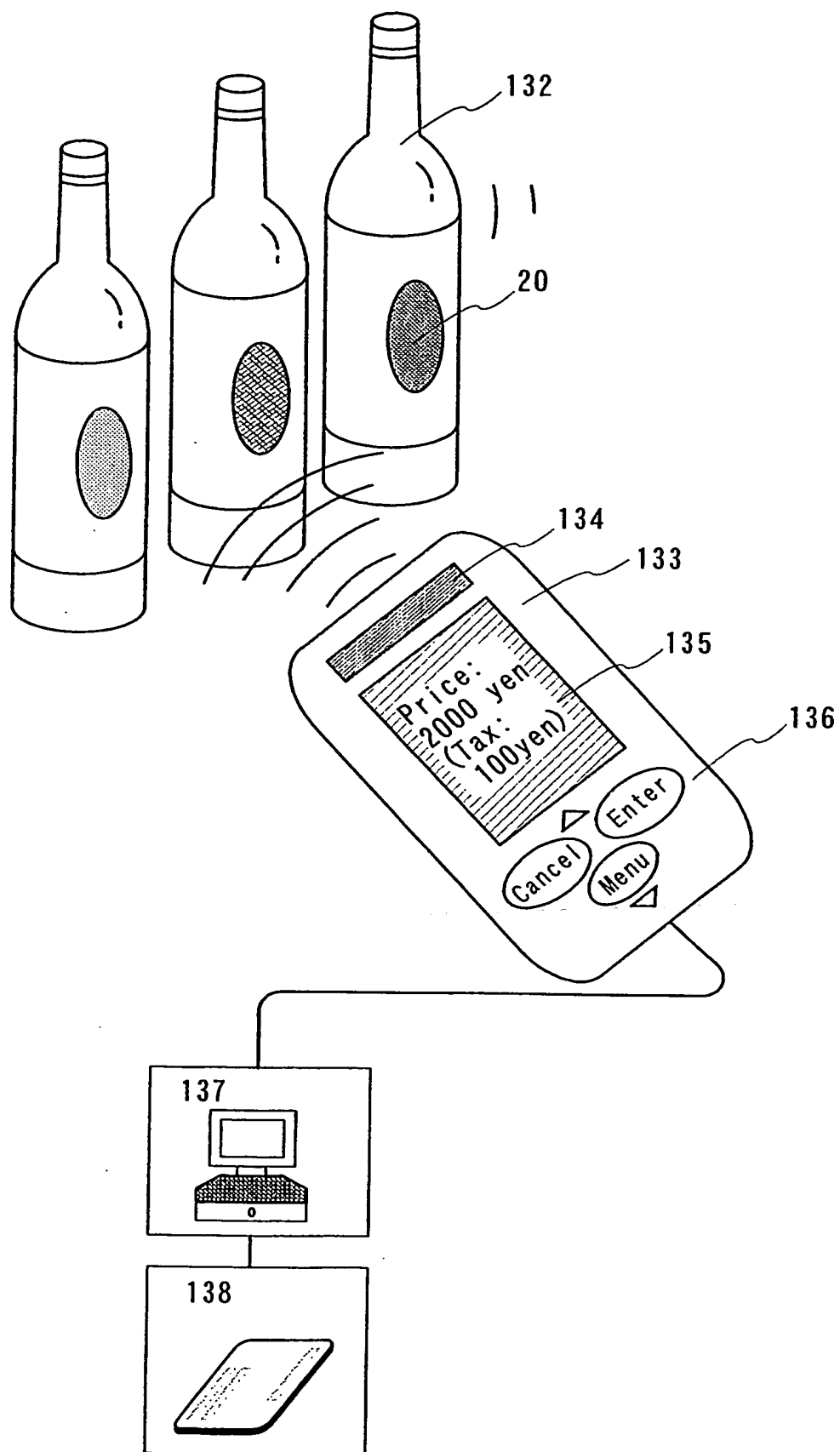


FIG. 30C



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FIG. 31



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FIG. 32A

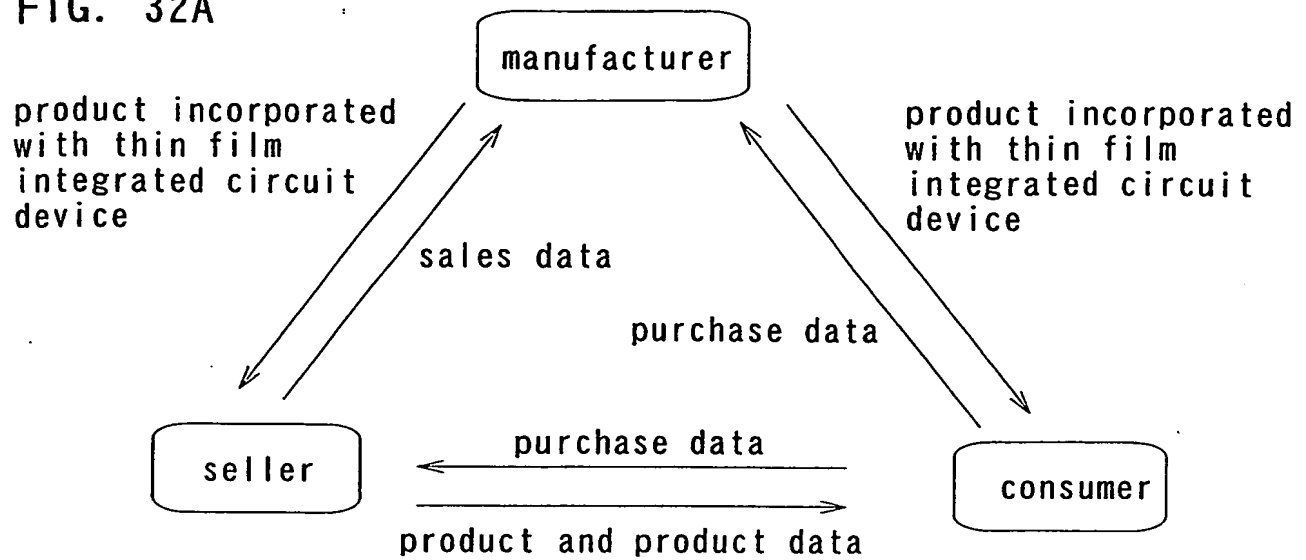
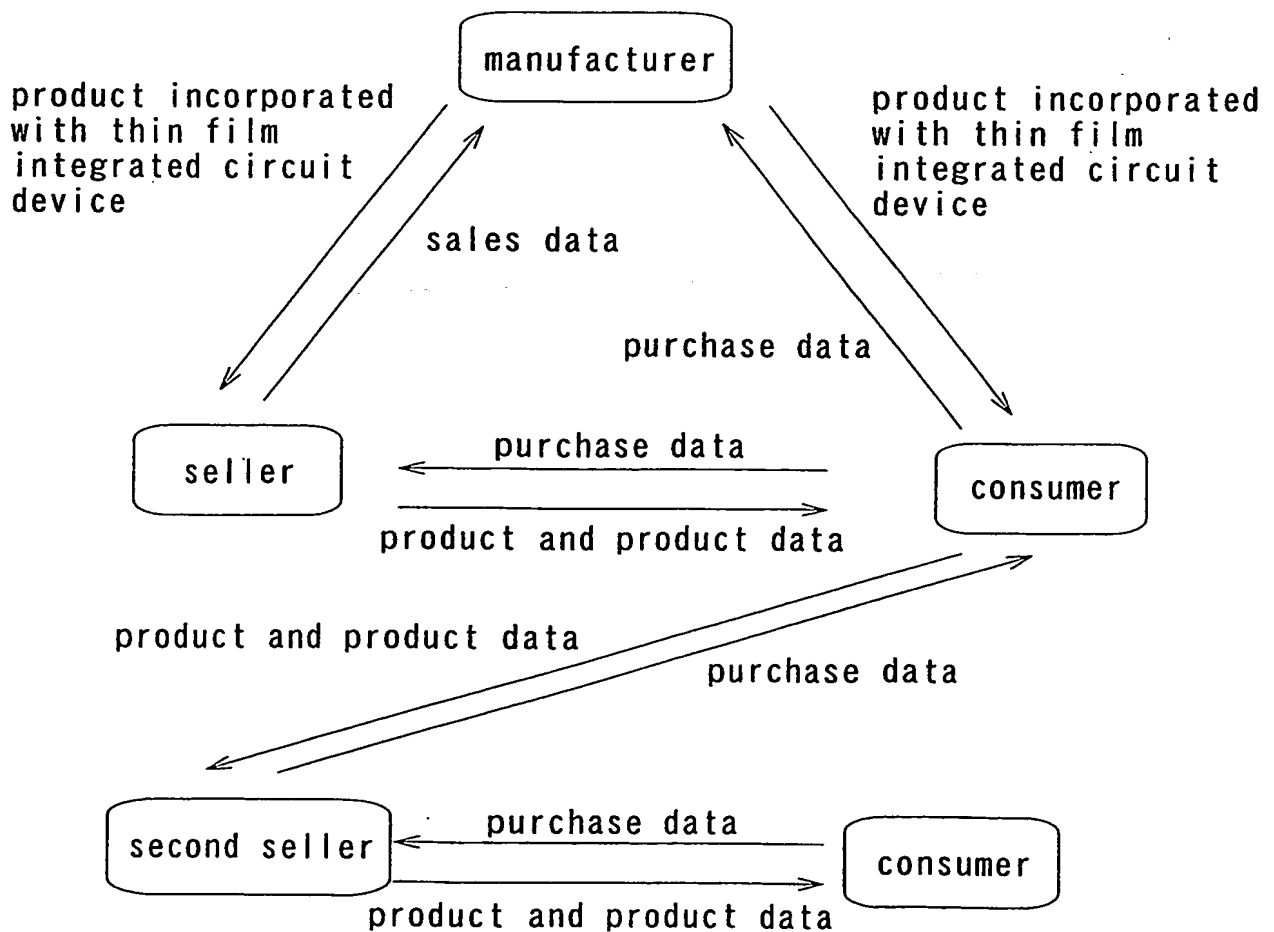
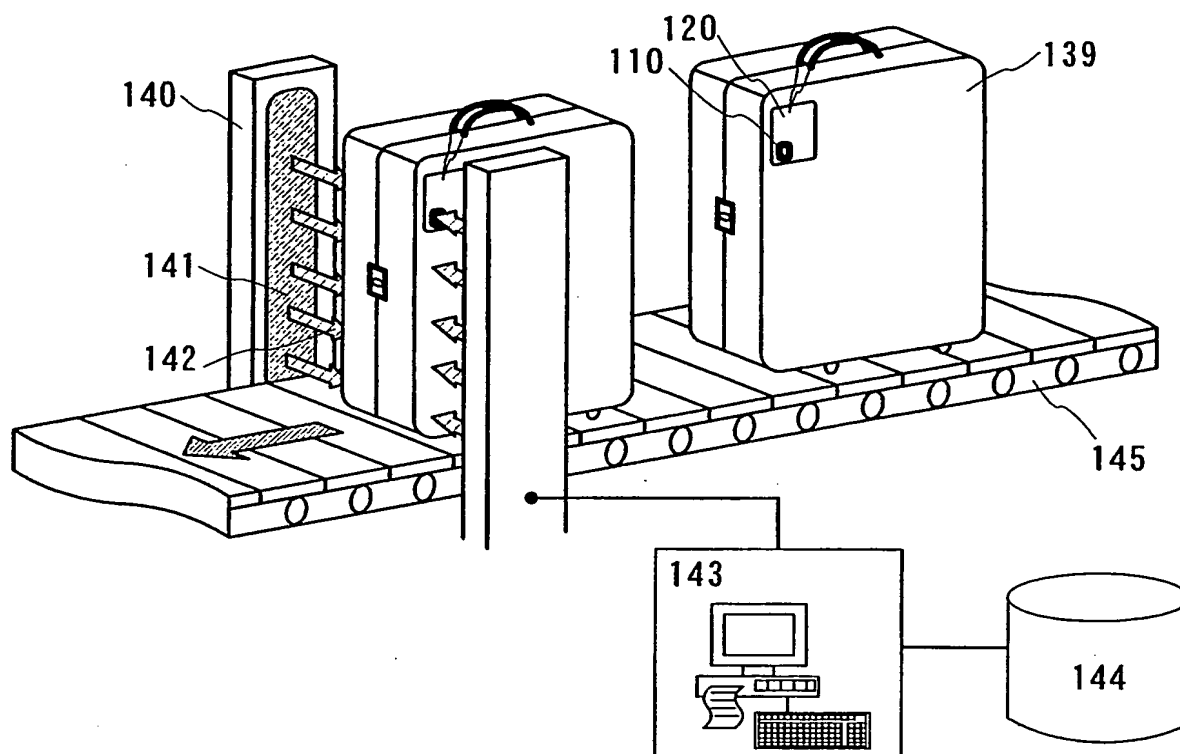


FIG. 32B



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FIG. 33



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FIG. 34A

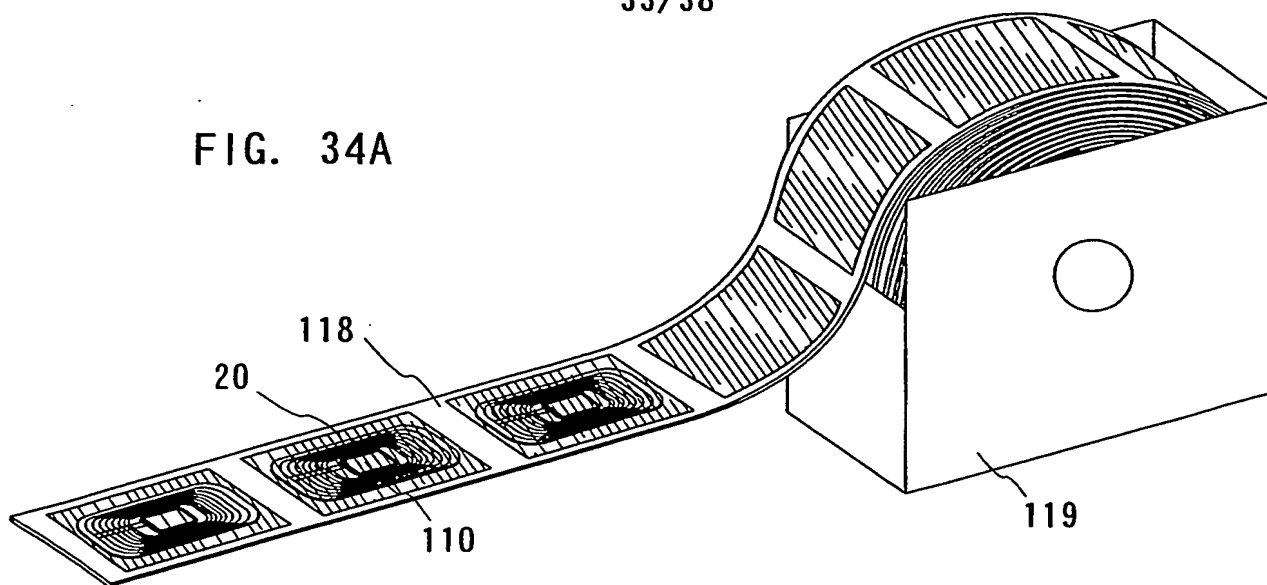


FIG. 34B

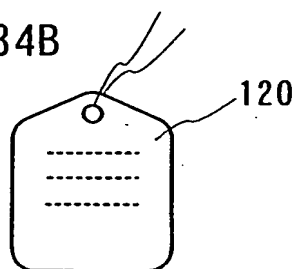


FIG. 34C

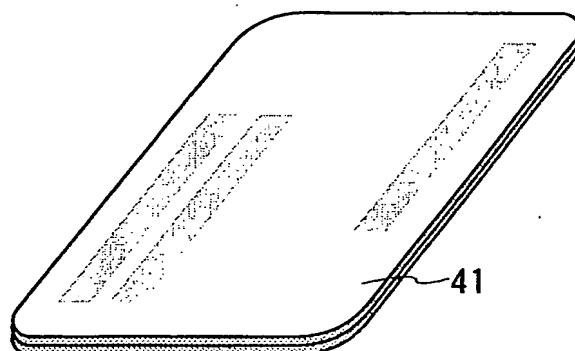


FIG. 34D

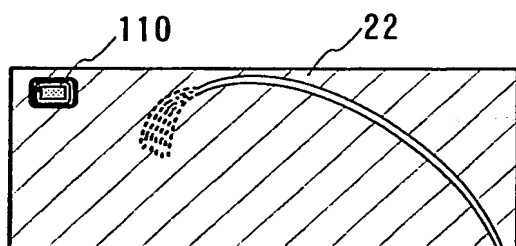
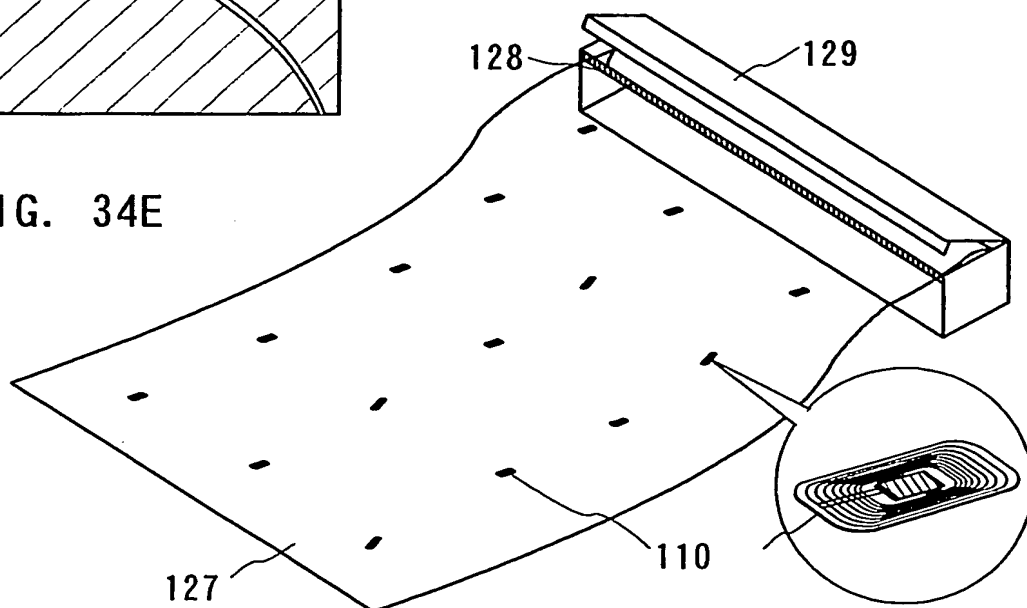


FIG. 34E



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FIG. 35A

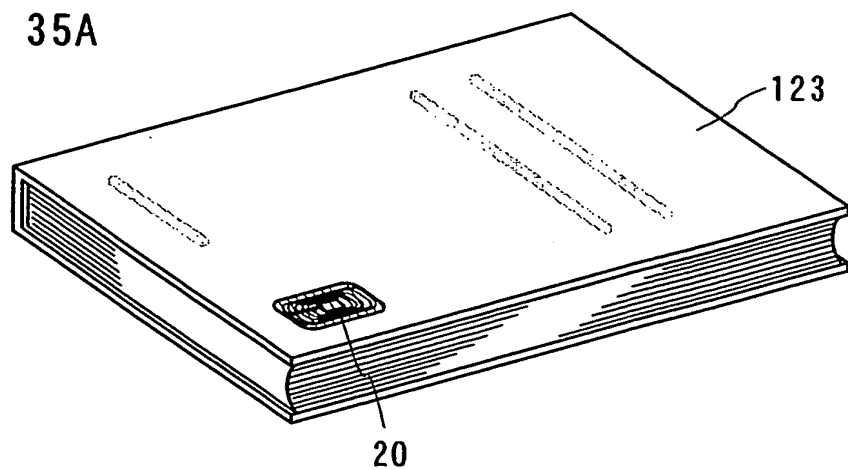


FIG. 35B

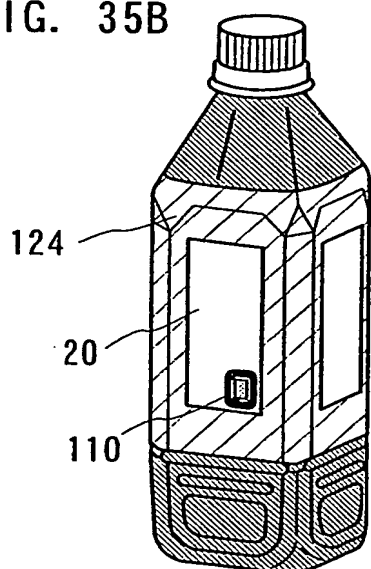


FIG. 35C

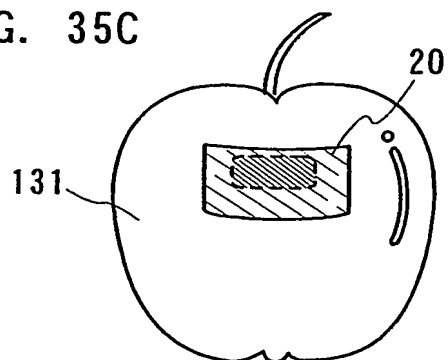
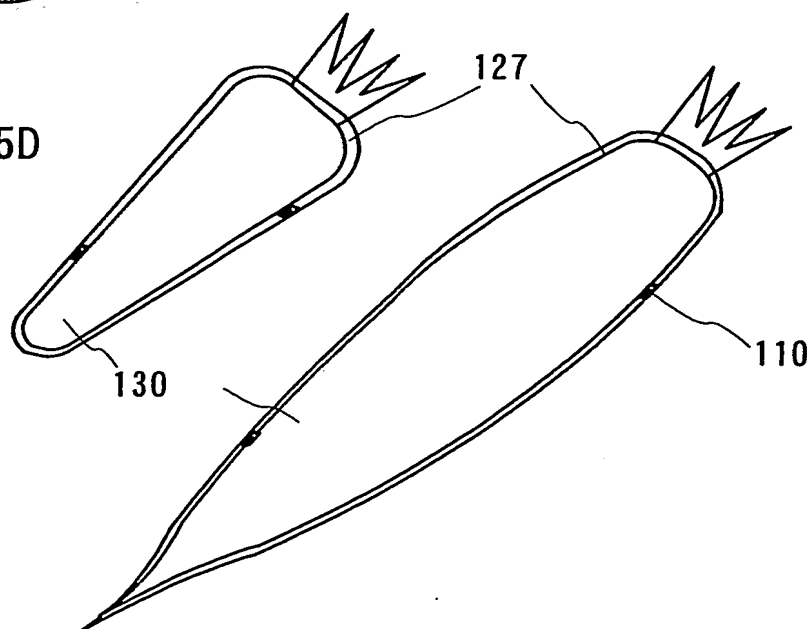


FIG. 35D



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FIG. 36A

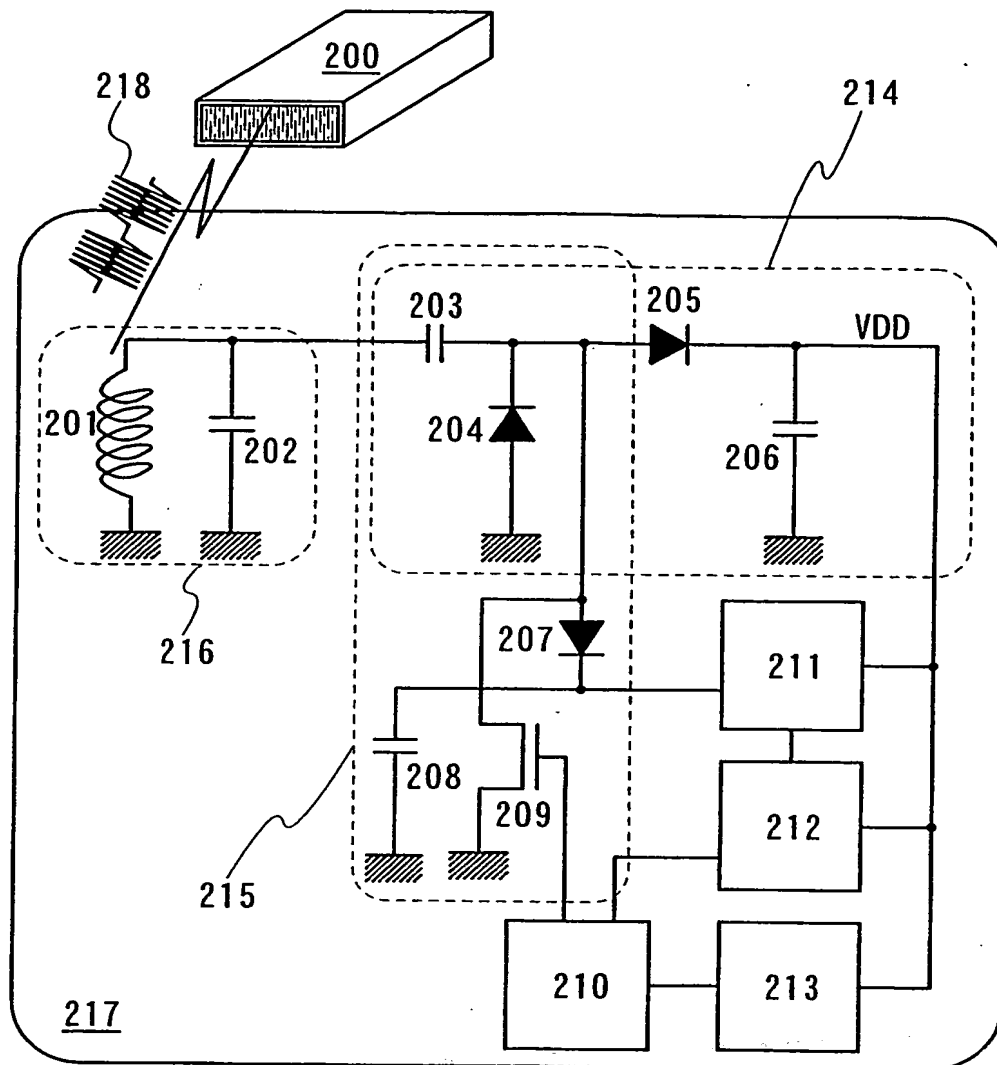
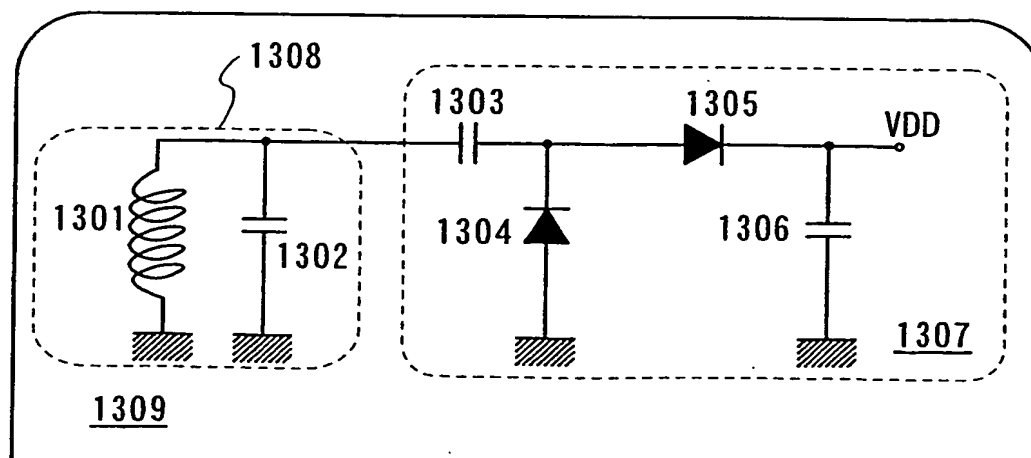


FIG. 36B



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EXPLANATION OF REFERENCE

10: label substratum, 11: antenna, 12: connecting pad, 13: thin film integrated circuit device, 14: image, 15: adhesive layer, 16: separating sheet, 17: coating layer, 18: cross wiring, 19: contact portion, 20: ID label, 21: connecting wiring, 21a: connecting wiring, 21b: connecting wiring, 21c: connecting wiring, 22: anisotropic conductive film, 23: TFT, 24: small vacuum pin set, 25: pin, 26: adhesive layer, 27: insulating layer, 28: contact portion, 29: TFT forming region, 30a: interlayer film, 30b: interlayer film, 31: protective film, 32: internal substratum, 33: surface, 35: protective layer, 36: adhesive layer, 34: protective layer, 37a: top card substratum, 37b: bottom card substratum, 38: adhesive layer, 39: adhesive layer, 40: coating layer, 41: ID card, 42a: top substratum, 42b: bottom substratum, 43a: top substratum, 43b: bottom substratum, 44: internal substratum, 45: film layer, 46: antenna integrated thin film integrated circuit device, 47: antenna, 48: thin film integrated circuit device, 51: wiring, 51a: wiring, 51b: wiring, 52: cross wiring, 53: interlayer film, 54: protective film, 54a: protective layer, 55: protective film, 56: gate electrode, 57: semiconductor layer, 58: gate insulating film, 60: substrate, 61: peeling layer, 63: resist, 64: impurity element, 65: low concentration impurity region, 66: resist, 67: impurity element, 68: high concentration impurity region, 69: n-type TFT, 70: p-type, 73: CPU, 74: memory, 75: insulating film, 76: sidewall, 77: resist, 78: impurity element, 79: impurity element, 80: terminal portion, 81: groove, 82: projection, 83: jig, 84: adhesive, 85: aperture, 86: gas, 87: resist, 88: substrate, 89: planarizing film, 90: silicon wafer, 91: oxide film, 92: thermal oxide silicon substrate, 93: single crystalline silicon substrate, 94: oxide film, 95: single crystalline silicon layer, 96: SIMOX substrate, 97: tray, 98: pin, 99: substrate as a tray, 100: bell jar, 101: substrate,

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102: heater, 103: exhaust pipe, 104: flexible substrate, 105: antenna, 105a: top antenna, 105b: bottom antenna, 106: connecting pad, 107: IDF chip, 108: connecting terminal, 109a: top connecting wiring, 109b: bottom connecting terminal, 110: IDF chip, 111: alignment marker, 113: adhesive, 114: UV ray, 115: source region, 116: channel region, 117: drain region, 118: label mounting, 119: box, 120: ID tag, 122: coupon bond, 123: book, 124: plastic bottle, 127: wrapping film, 128: cutter, 129: box, 130: vegetables, 131: fruit, 132: product, 133: R/W, 134: antenna portion, 135: display portion, 136: operating key, 137: POS system, 138: private account, 139: baggage, 140: reader/writer, 141: antenna, 142: radio wave, 143: computer, 144: database, 145: conveyer, 170: main body of reader/writer, 171: sensor portion, 172: product, 180: main body of portable phone, 181: sensor portion, 183: display portion, 190: main body of reader, 191: sensor portion, 193: display portion, 200: reader/writer, 201: antenna wiring, 202: antenna capacitor, 203: capacitor, 204: diode, 205: diode, 206: capacitor, 207: diode, 208: capacitor, 209: switching element, 210: logic circuit, 211: amplifier, 212: clock generating circuit and decoder, 213: memory, 214: power source circuit, 215: input/output circuit, 216: antenna circuit, 217: IDF chip, 218: radio wave, 300: label paper supply means, 301: ACF supply means, 302: IDF chip adhering means, 303: adhesive layer supply means, 304: separating sheet supply means, 305: label roll up means, 306: label separating means, 307: collecting means, 308: substratum supply means, 309: substratum separating means, 310: laminating apparatus, 400: input antenna, 401: output antenna, 402: input interface, 403: output interface, 404: CPU, 405: coprocessor, 406: ROM, 407: RAM, 408: non-volatile memory, 409: bus, 410: thin film integrated circuit device, 411: non-contact integrated circuit device, 412: radio wave, 414: reader/writer (R/W), 415: database, 416: integrated circuit, 417: output interface, 418: output antenna, 419: computer, 420: rectifying circuit,

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421: demodulating circuit, 423: modulating circuit, 424: amplifier, 425: input antenna, 426: input interface, 427: controller, 900: control portion, 901: arithmetic unit, 902: arithmetic register, 903: A register, 904: B register, 905: main memory, 906: program memory, 907: work memory, 908: data memory, 910: register group, 911: address control portion, 912: instruction register, 913: instruction decoder, 914: input/output interface, 915: internal bus, 916: data bus, 917: address bus, 918: control bus, 919: CPU, 1301: antenna wiring, 1302: antenna capacitor, 1303: capacitor, 1304: diode, 1305: diode, 1306: capacitor, 1307: power source circuit, 1308: antenna circuit, 1309: IDF chip